

Service Manual

S88

Level 1-3



Release	Date	Department	Notes to change
R 1.0	15.02.2006	BenQ Mobile CC S CES	New document

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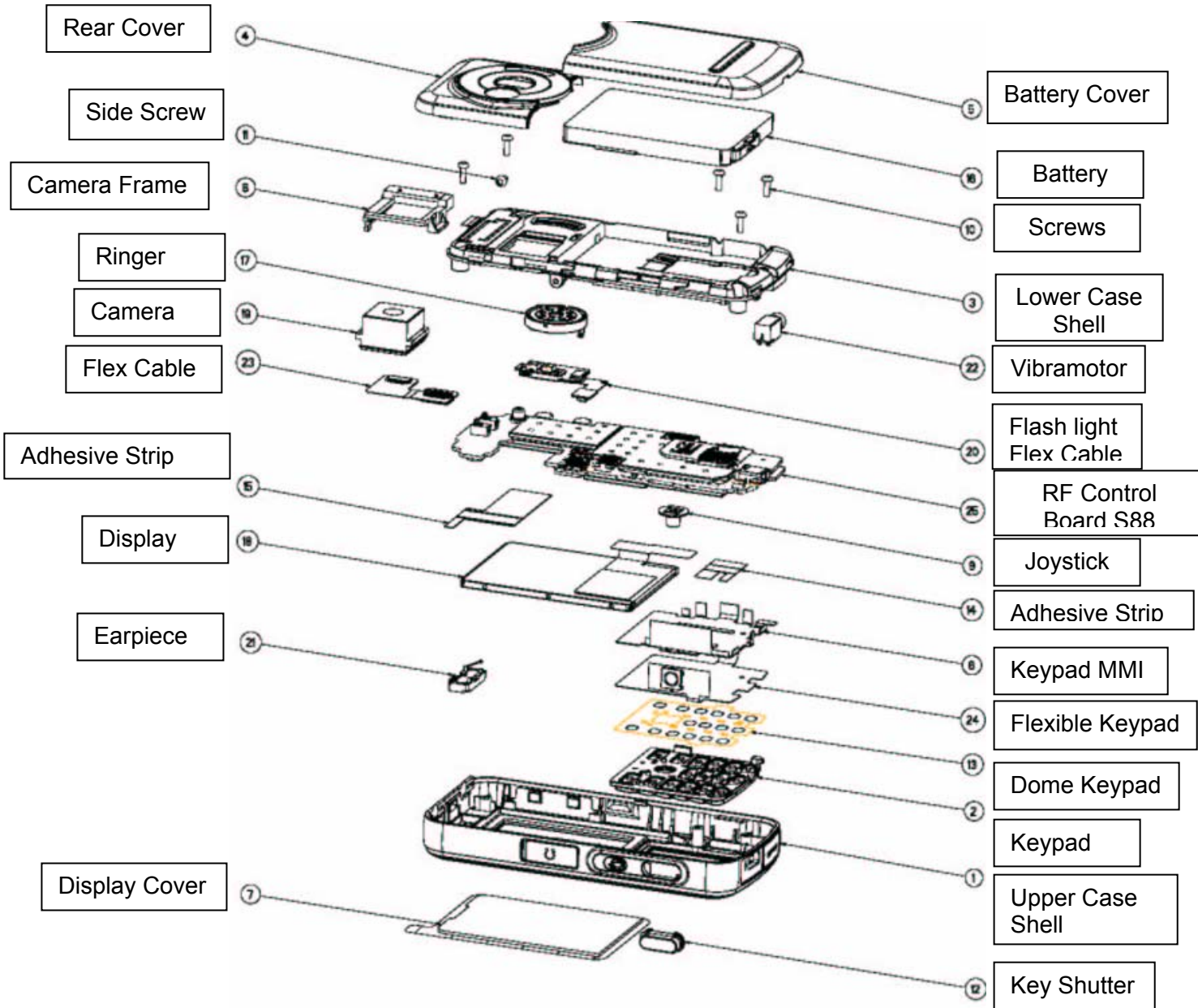
1 Key Feature

System	<ul style="list-style-type: none"> • Tri-band handset (GSM900/DCS1800/PCS1900) or (GSM850/DCS1800/PCS1900) with internal antenna
Battery	<ul style="list-style-type: none"> • Li – Ion 920mAh battery
Stand – by Time	<ul style="list-style-type: none"> • Up to 200 hours
Talking Time	<ul style="list-style-type: none"> • 130min~450min
Memory	<ul style="list-style-type: none"> • NOR flash: 128MB • NAND flash: 256MB • Pseudo SRAM: 64MB • Mobile SDRAM: 128MB
External Memory	<ul style="list-style-type: none"> • Micro SD/Transflash
Display	<ul style="list-style-type: none"> • Display mode: Active Matrix, OLED • Active area: 31.152mm x 38.94mm • Pixel pitch: 0.177mm x 0.177mm • Number of Colours: 260K
Keypad	<ul style="list-style-type: none"> • 12 numerical key (including *,#) • 5-way navigation key • Soft keys: Left and Right • Send key • End/Power key
Function key	<ul style="list-style-type: none"> • Side keys: <ul style="list-style-type: none"> ○ Volume keys ○ Camera/Video mode switch button ○ Camera shutter button
Camera	<ul style="list-style-type: none"> • 2.0 mega pixel; CMOS Auto Focus camera for image and video recording
Connectivity	<ul style="list-style-type: none"> • USB 1.1; Bluetooth
FM Radio	<ul style="list-style-type: none"> • Embedded in Mobile Phone
Camcorder	<ul style="list-style-type: none"> • Support MPEG 4/ 3GP
MP3 – Player	<ul style="list-style-type: none"> • Support MP3/AAC • Equalizer

2 Unit Description of S88



3 Exploded View of S88



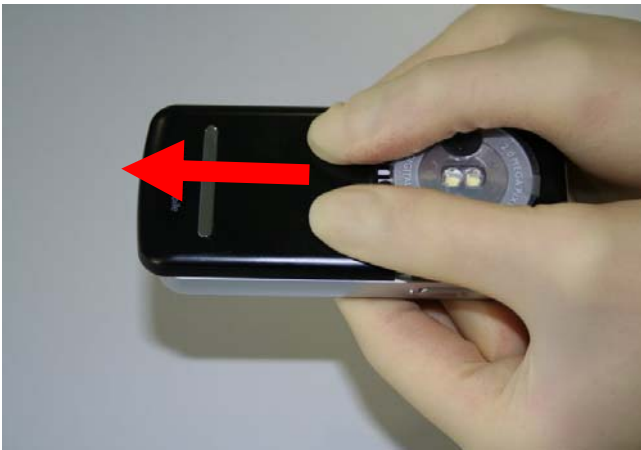

4 Disassembly of S88




All repairs as well as disassembling and assembling have to be carried out in an ESD protected environment and with ESD protected equipment/tools. For all activities the international ESD regulations have to be considered.




For more details please check information in c – market




<https://market.benqmobile.com/SO/welcome.lookup.asp>




There you can find the document “ESD Guideline”.




<p>Step 1</p> 	<p>Remove Battery Cover.</p>
<p>Step 2</p> 	




<p>Step 3</p> 	<p>Remove Battery.</p>
<p>Step 4</p> 	
<p>Step 5</p> 	<p>Open Handset – Cover to remove Side Screw. Use the Torque – Screwdriver T5.</p>



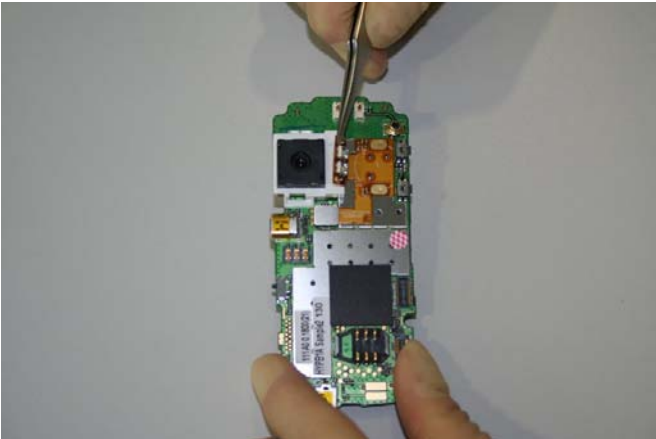
<p>Step 6</p> 	<p>Remove Screw.</p>
<p>Step 7</p> 	<p>Remove Camera Cover by using Alternative Opening Tool carefully.</p>
<p>Step 8</p> 	

<p>Step 9</p> 	<p>Remove screws with the Torque – Screwdriver. T5</p>
<p>Step 10</p> 	<p>Remove Lower Case Shell from Upper Case Shell with Alternative Opening Tool. Be very careful.</p>
<p>Step 11</p> 	

<p>Step 12</p> 	<p>Remove Ringer by using Tweezers.</p>
<p>Step 13</p> 	<p>Remove Vibramotor by using Tweezers.</p>
<p>Step 14</p> 	<p>Use Tweezers to disconnect the Flex Cable from the RF Control Board sockets.</p>

<p>Step 15</p> 	
<p>Step 16</p> 	<p>Pull the Memory Card Cover forward to remove the RF Control Board.</p>
<p>Step 17</p> 	<p>Remove RF Control Board from Lower Case with Alternative Opening Tool carefully.</p>

<p>Step 18</p> 	
<p>Step 19</p> 	<p>Disconnect the Adhesive Strip with Flex Cable from the RF Control Board by using Tweezers carefully.</p>
<p>Step 20</p> 	

<p>Step 21</p> 	
<p>Step 22</p> 	
<p>Step 23</p> 	<p>Disconnect Flash light Flex Cable from Camera Frame. Take care of the Flex Cable!!!</p>

Step 24

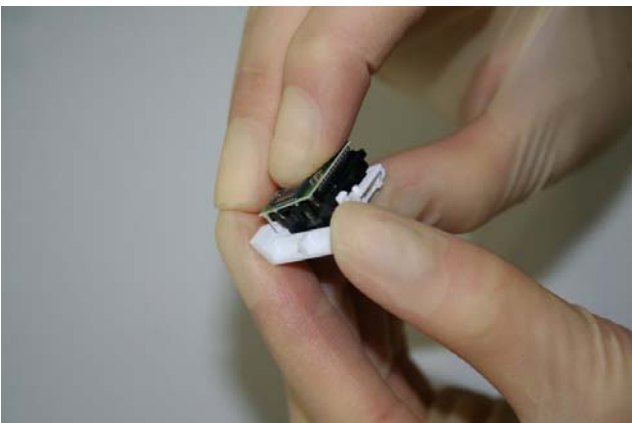


Remove Camera with Camera Frame by pressing the hooks together.

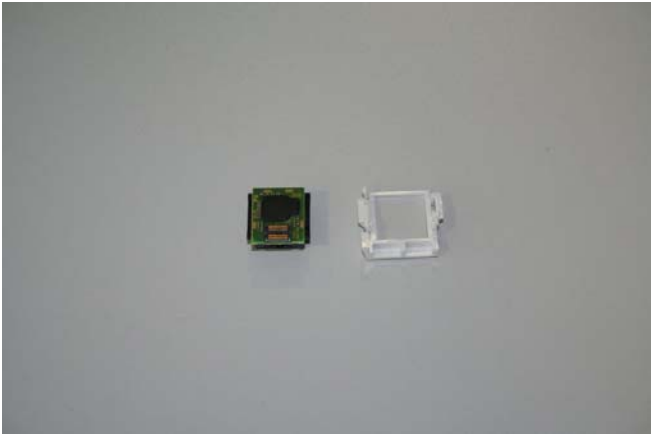
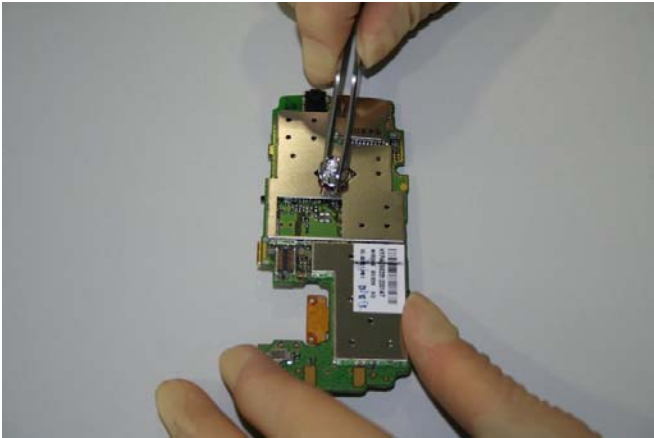

Step 25

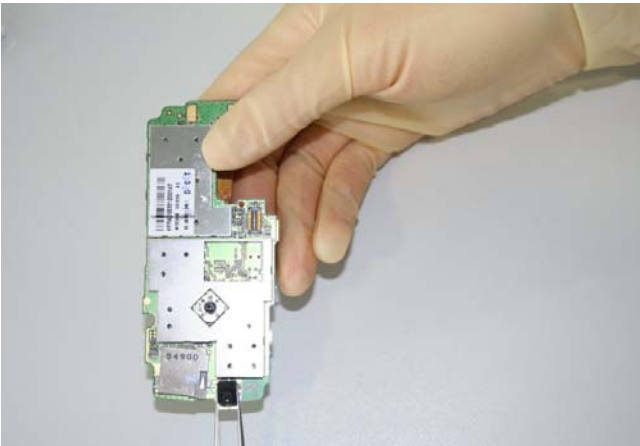
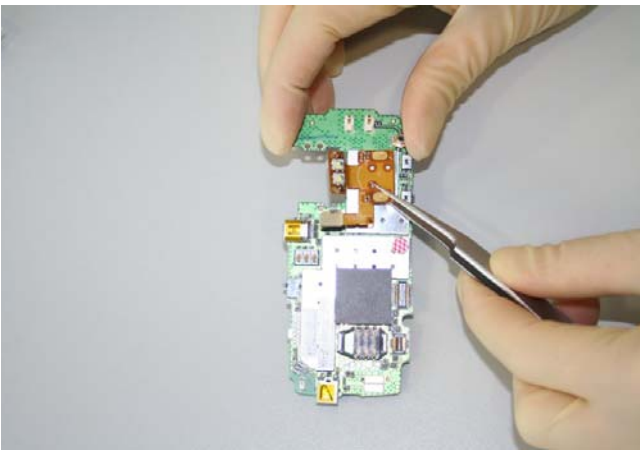






Step 26



Disassemble Camera Frame from Camera.

<p>Step 27</p> 	
<p>Step 28</p> 	<p>Remove Joystick by using Tweezers.</p>
<p>Step 29</p> 	

<p>Step 30</p> 	<p>Remove Microphone Shielding by using Tweezers carefully.</p>
<p>Step 31</p> 	<p>Remove the Flash light Flex Cable from the RF Control Board. Use Tweezers very carefully!</p>
<p>Step 32</p> 	<p>Remove the Display by using the Alternative Opening Tool.</p>

<p>Step 30</p> 	<p>To avoid scratches it is mandatory to place a protection foil onto the Display!!!</p>
<p>Step 31</p> 	<p>Use Alternative Opening Tool to remove the Keypad MMI.</p>
<p>Step 32</p> 	<p>Remove Keypad by using Alternative Opening Tool.</p>

Step 33






Step 34

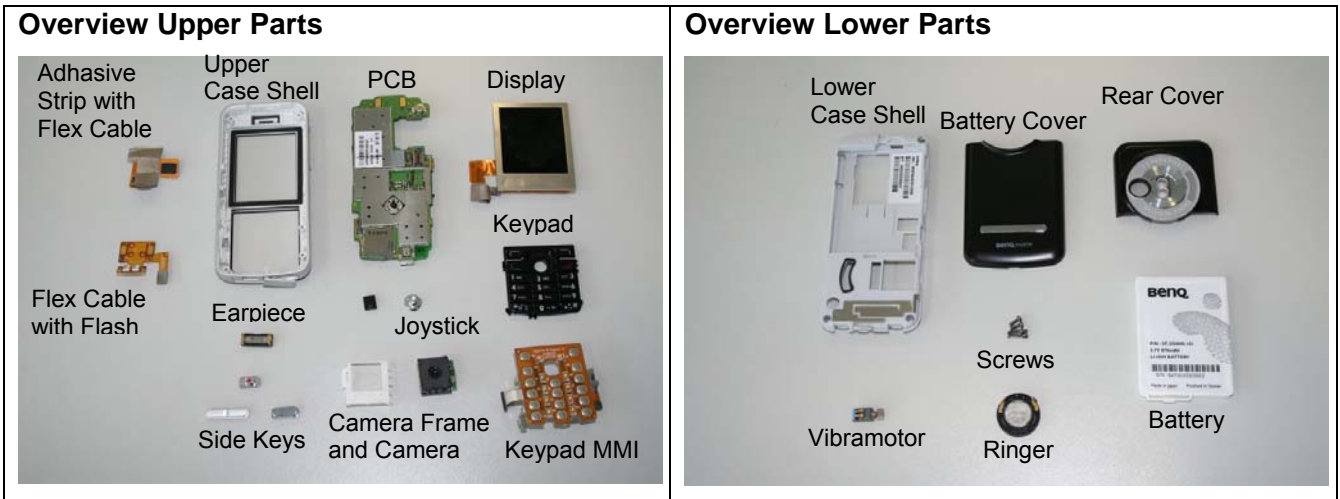


Remove the Side Keys by pushing them outside the frames.



Step 35







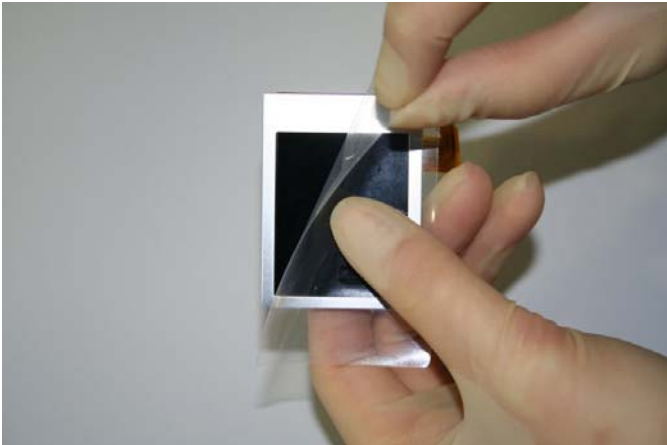

<p>Step 36</p> 	
<p>Step 37</p> 	<p>Remove Camera – Video - Key by using Tweezers.</p>
<p>Step 38</p> 	<p>Remove the Earpiece with the Alternative Opening Tool.</p>

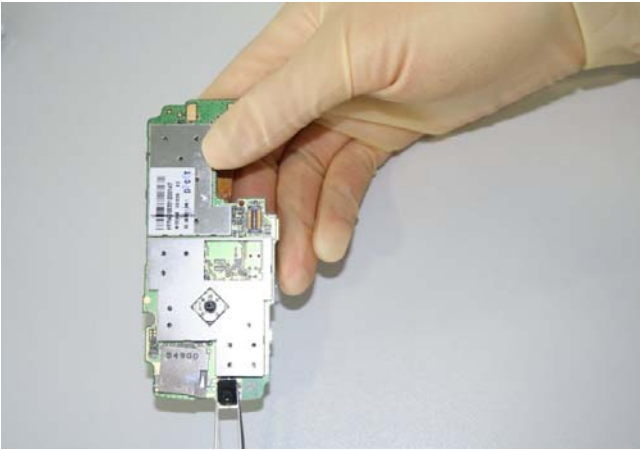
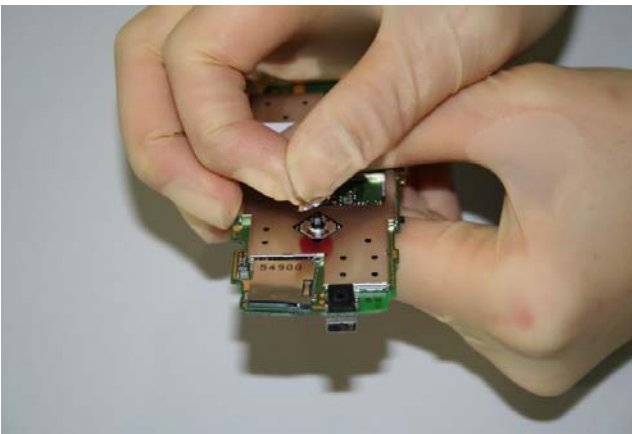
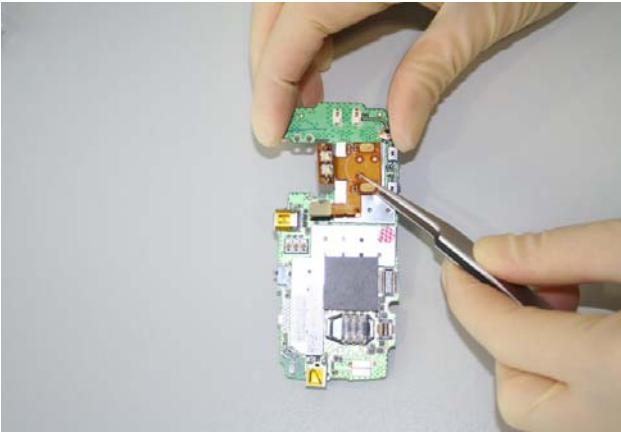


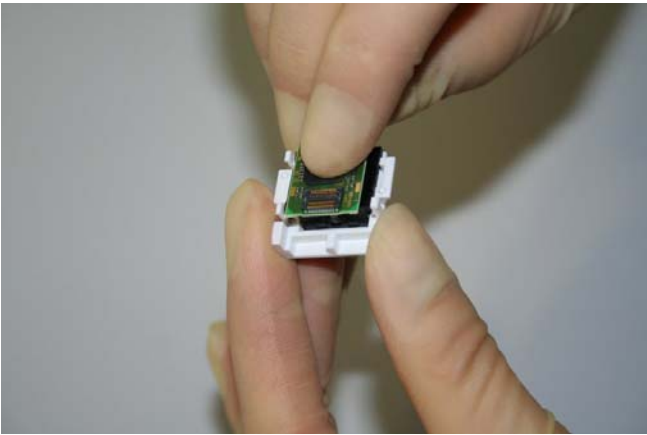

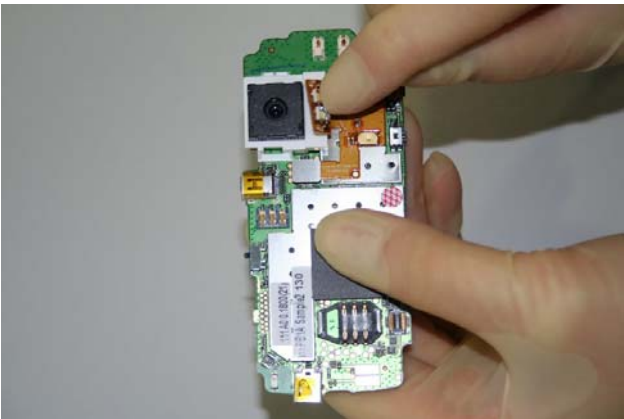
5 Assembly of S88


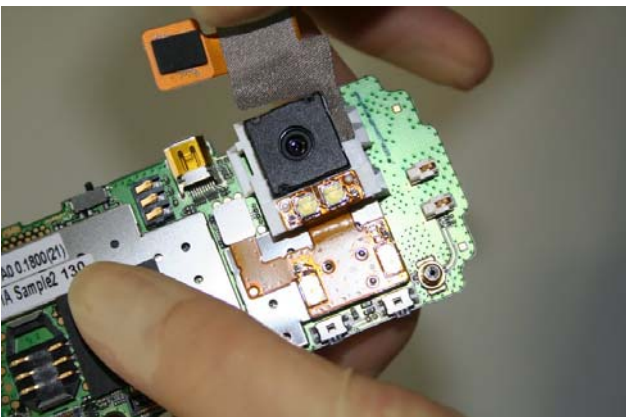
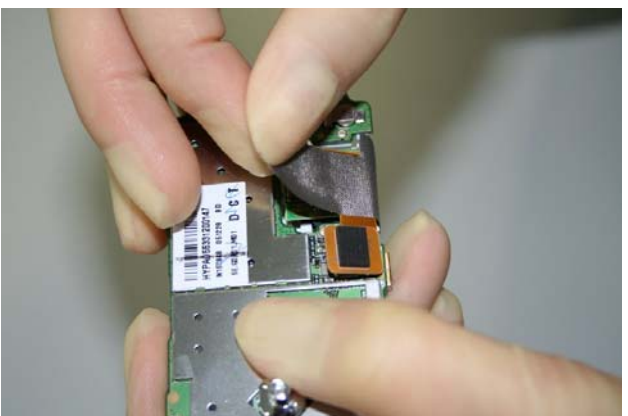
<p>Step 1</p> 	<p>Assemble Earpiece by using Tweezers.</p>
<p>Step 2</p> 	<p>Assemble Camera – Video – Key by using Tweezers.</p>




<p>Step 3</p> 	<p>Assemble Side Keys by using Tweezers.</p>
<p>Step 4</p> 	
<p>Step 5</p> 	<p>Assemble Keypad.</p>



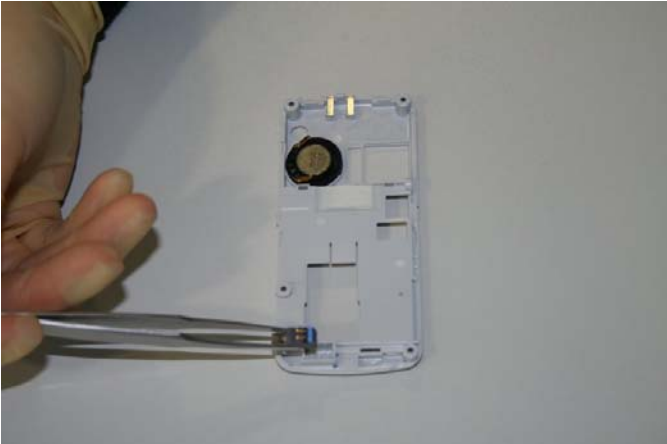
<p>Step 6</p> 	<p>Assemble Keypad MMI.</p>
<p>Step 7</p> 	<p>Remove the Display Foil from the Display.</p>
<p>Step 8</p> 	<p>Assemble the Display in the given frame.</p>




<p>Step 9</p> 	<p>Use Tweezers to assemble the Microphone Shielding.</p>
<p>Step 10</p> 	<p>Assemble Joystick.</p>
<p>Step 11</p> 	<p>Connect the Flash light Flex Cable with the RF Control Board. Take care of the Flex Cable!</p>




<p>Step 12</p> 	<p>Assemble the Camera into the Camera Frame.</p>
<p>Step 13</p> 	<p>Fit the Assembled Camera into the cut out of the RF Control Board.</p>
<p>Step 14</p> 	<p>Clip the Flash lights onto the Camera Frame.</p>

<p>Step 15</p> 	<p>Fix the Adhesive Strip onto the Camera Frame.</p>
<p>Step 16</p> 	
<p>Step 17</p> 	<p>Turn the RF Control Board and fix the end of the Adhesive Strip on the shielding plate.</p>

<p>Step 15</p> 	
<p>Step 16</p> 	<p>Fix the RF Control Board into the Upper Case Shell.</p>
<p>Step 14</p> 	<p>Connect the Flex Cable with the RF Control Board socket.</p>

<p>Step 15</p> 	<p>Connect the Flex Cable with the RF Control Board socket.</p>
<p>Step 16</p> 	<p>Assemble the Ringer in the given frame of the Lower Case Shell.</p>
<p>Step 17</p> 	<p>Assemble the Vibrator in the given frame of the Lower Case Shell.</p>

<p>Step 18</p> 	<p>Assemble Upper Case Shell with Lower Case Shell.</p>
<p>Step 19</p> 	
<p>Step 20</p> 	<p>Place screws with the Torque – Screwdriver. T5.</p>

<p>Step 21</p> 	<p>Assemble Rear Cover.</p>
<p>Step 22</p> 	<p>Assemble Battery.</p>
<p>Step 23</p> 	<p>Place side screw. T5</p>

Step 24



Assemble Battery Cover.


6 BenQ Service Equipment User Manual

Introduction

Every LSO repairing BenQ handset must ensure that the quality standards are observed. BenQ has developed an automatic testing system that will perform all necessary measurements. This testing system is known as:

BenQ Mobile Service Equipment

- For disassembling / assembling

	<p style="text-align: center;">Torque – Screwdriver Part Number: F 30032 – P 228 – A1</p>
	<p style="text-align: center;">Opening tool (Case opening without destroying) Part Number: F 30032 – P 38 – A1</p>
	<p style="text-align: center;">Alternative Opening tool Part Number: F30032 – P583 – A1</p>
	<p style="text-align: center;">Tweezers</p>

- For testing

All mobile phones have to be tested with the GRT – Software. The service partner is responsible to ensure that all required hardware is available.

For additional Software and Hardware options as well as the supported GRT equipment, please check the GRT User manual.

<p>Technical Documentation</p>	<p style="text-align: right;">02/2006</p>
<p>TD_Repair_L2.5L_S88_R1.0.pdf</p>	<p style="text-align: right;">Page 31 of 61</p>

7 Setup of the Software

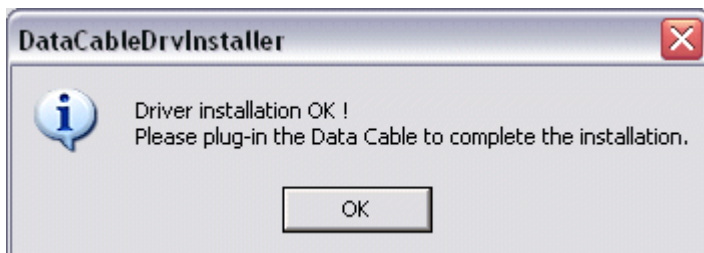
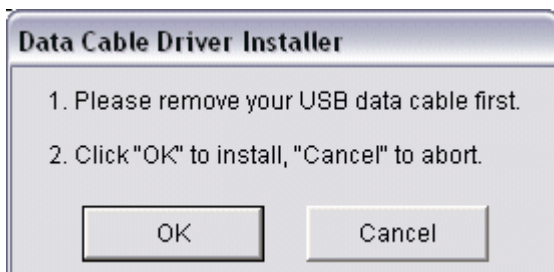
Download of the required software:

Download the driver, the XCSO software mobile software (core-software and language files) from the Technical Support Page:

<https://market.benqmobile.com/so/welcome.lookup.asp>

Installation of USB – Serial converter boot cable:

Start the "DataCableDrvInstaller.exe" file and follow the instructions of the installer.



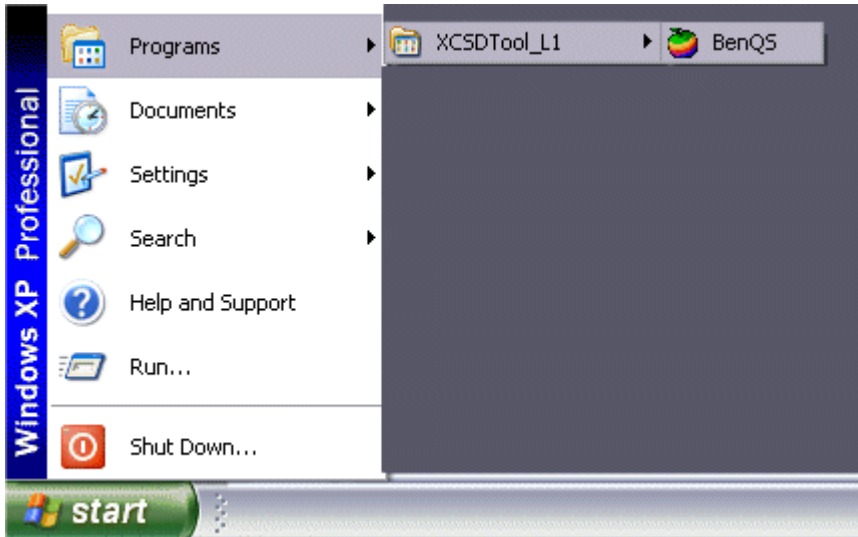
Plug in the Data cable and follow the installation instructions to complete the process.

**Check the Comport number of the data cable in the device manager.
(XCSO tool supports only Comport 1 to 10)**

Installation of XCSD tool:

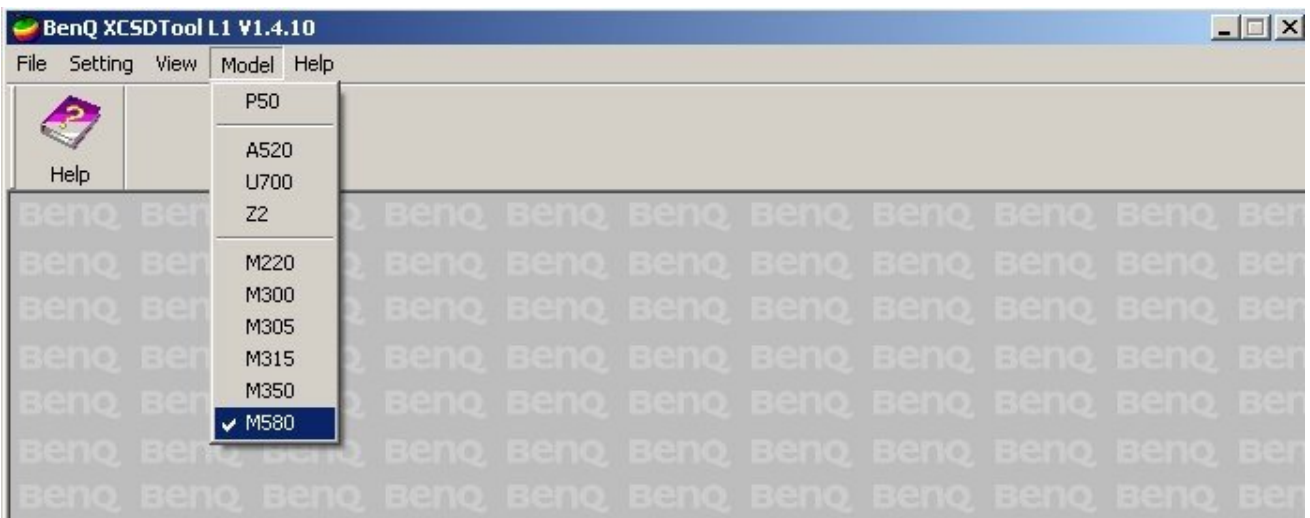
Start “setup.exe” file and follow the instructions.

The installer creates a shortcut in the start menu bar. Start – Programs – XCSDTool_L1 - BenQS

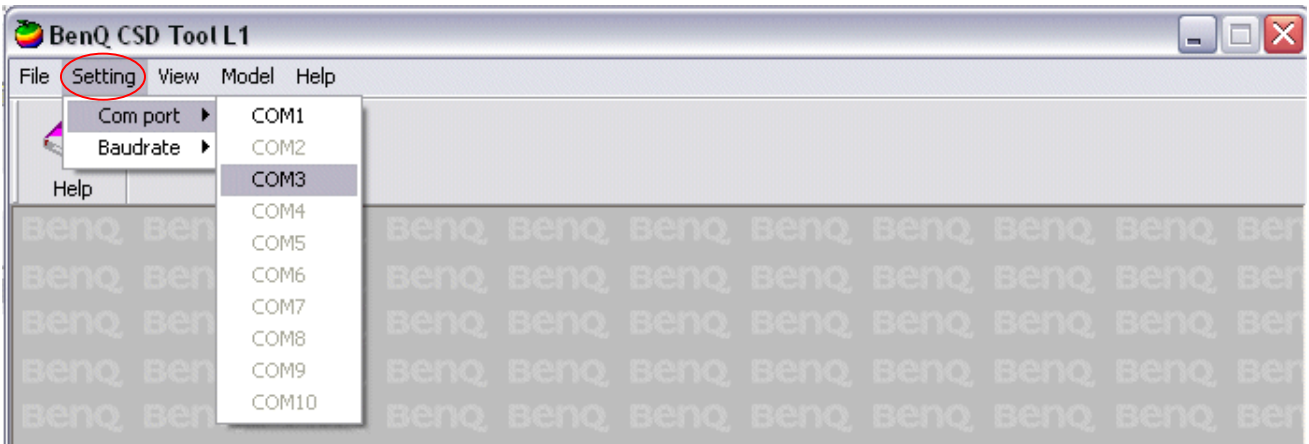


8 Software basic settings

- Start the software (BenQS.exe). The XCSD tool will be shown on the screen
- Select Model:

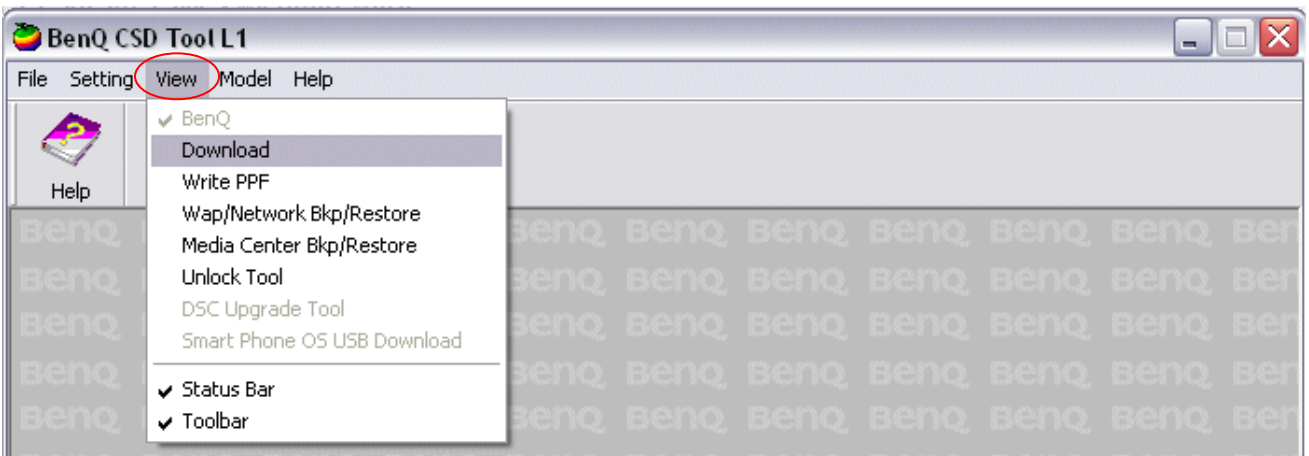


- Select Com port (Setting – Com port):

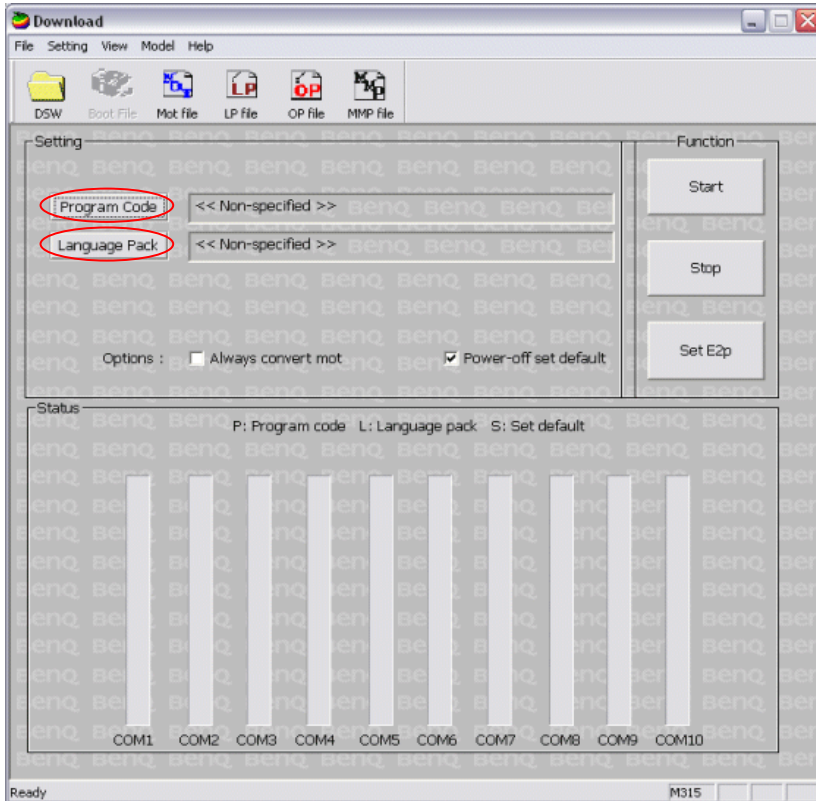


9 Software Download procedure

- Select Download Option (View – Download):



- Select Program Code (example: E22 1 11710.mot) and Language Pack (example E22 L 11711.mot)



Status bar colour scheme:

yellow	waiting for update
blue	update in progress
red	error occurred
black	Comport not available
green	Update successful

- Connect mobile phone with data cable. Phone must be switched off. Click on “Start” button and press the power on button on the handset to start the download. During download process status bar shows the state of the process of P = Program code, L = Language file and S = Set default (if activated). After successful SW download, the status bar of the used Com port is changed to green.

Erase of customer data:

Select the “Power-off set default” option to erase all customer data of the phone during the download process.

- Click the “Set E2p” to erase the customer data without software update.

SW files naming rules:

Program Code E2211710
 Language Pack E22L11711

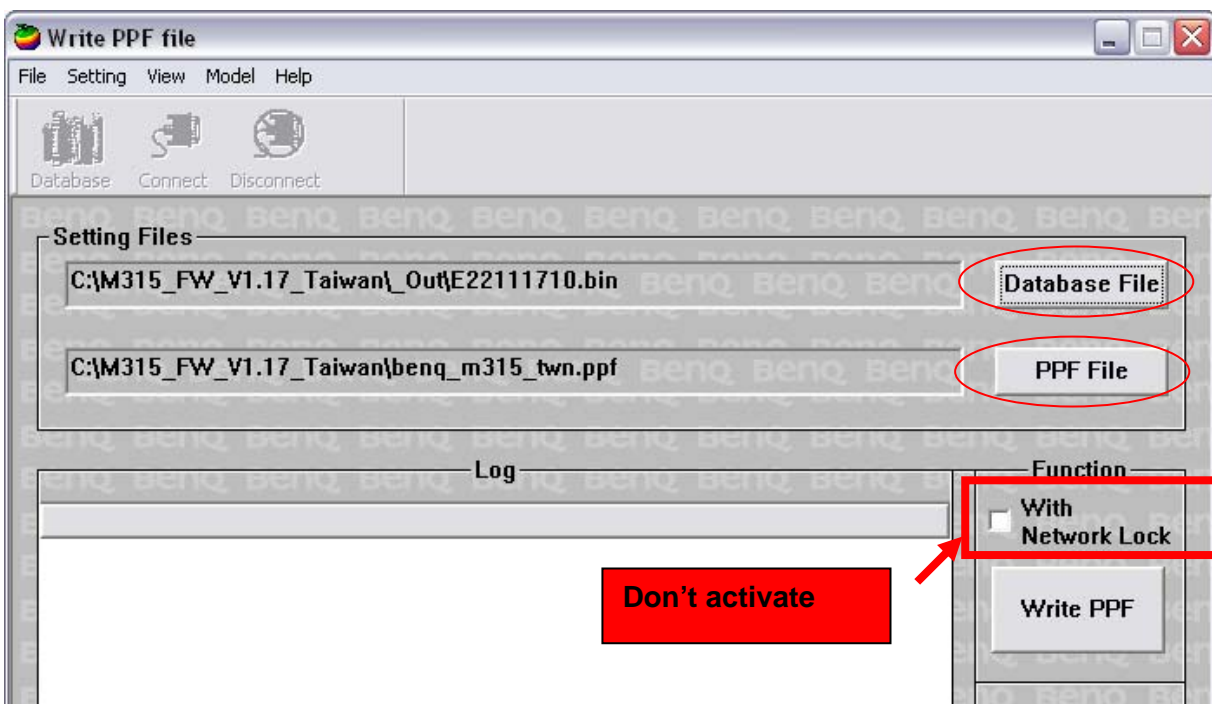
E22 Project name
 117 Program Code
 L Language Pack
 117 Version 1.17
 10/11 Program Code ID

10 Download PPF (Handset configuration)

- Select write PPF option (View – Write PPF):

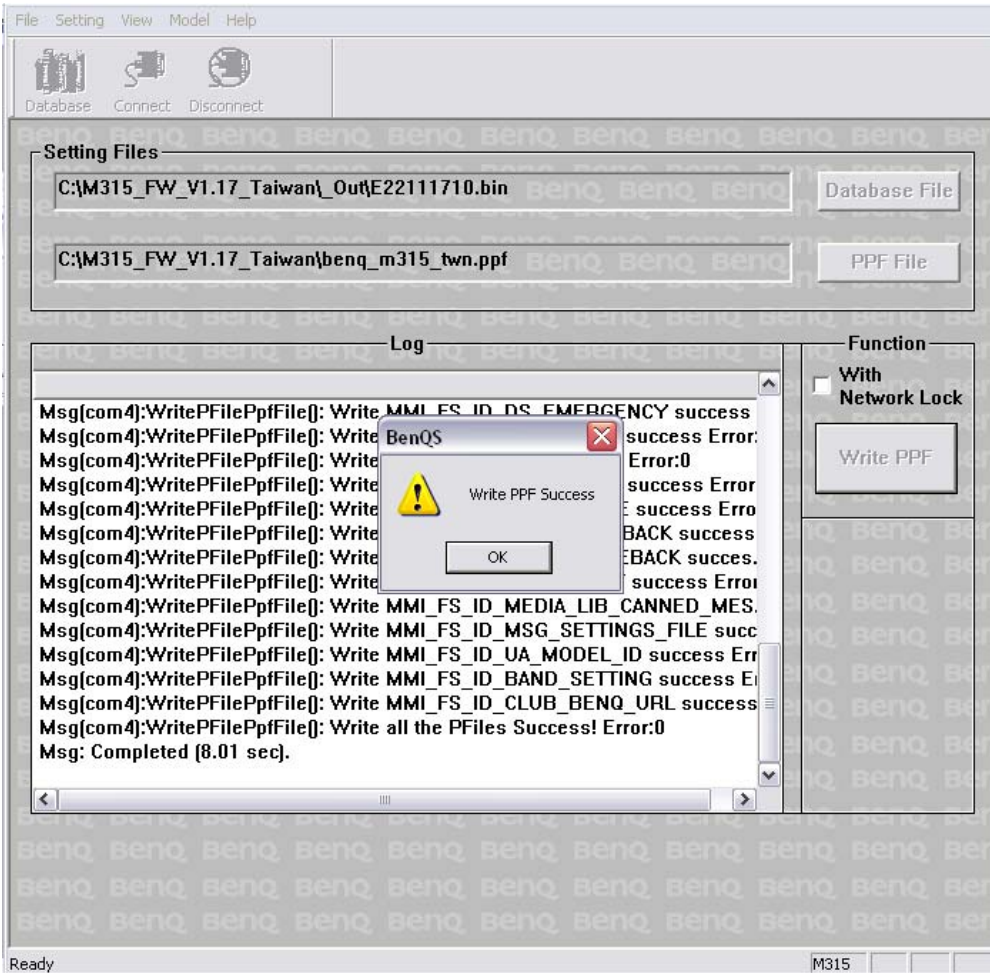


- Select Database File (example: E22111710.bin) and PPF File (example: benq_m315_twn.ppf)



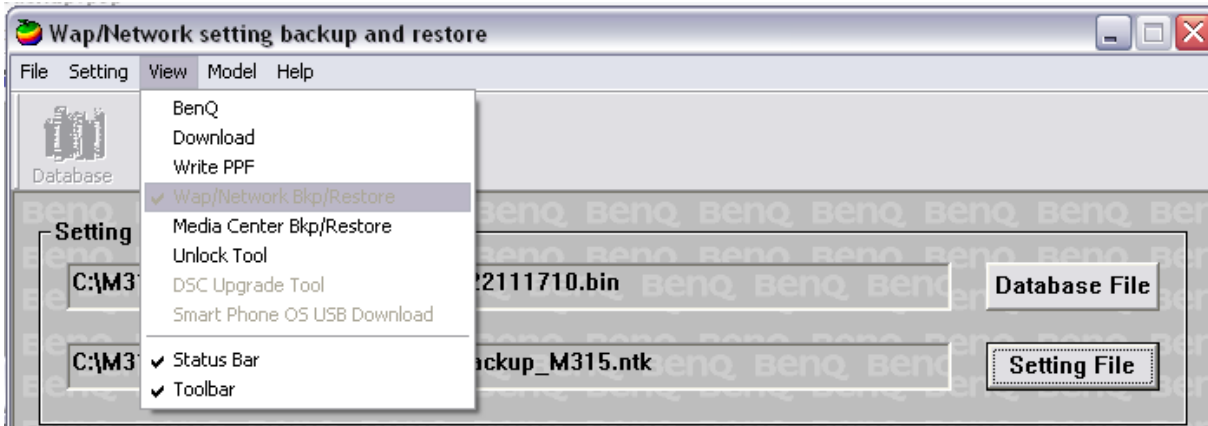
- Connect mobile phone with data cable. Phone must be switched on. Click to “Write PPF” button to start the process.

- Confirmation about successful write of PPF appears after process is completed.

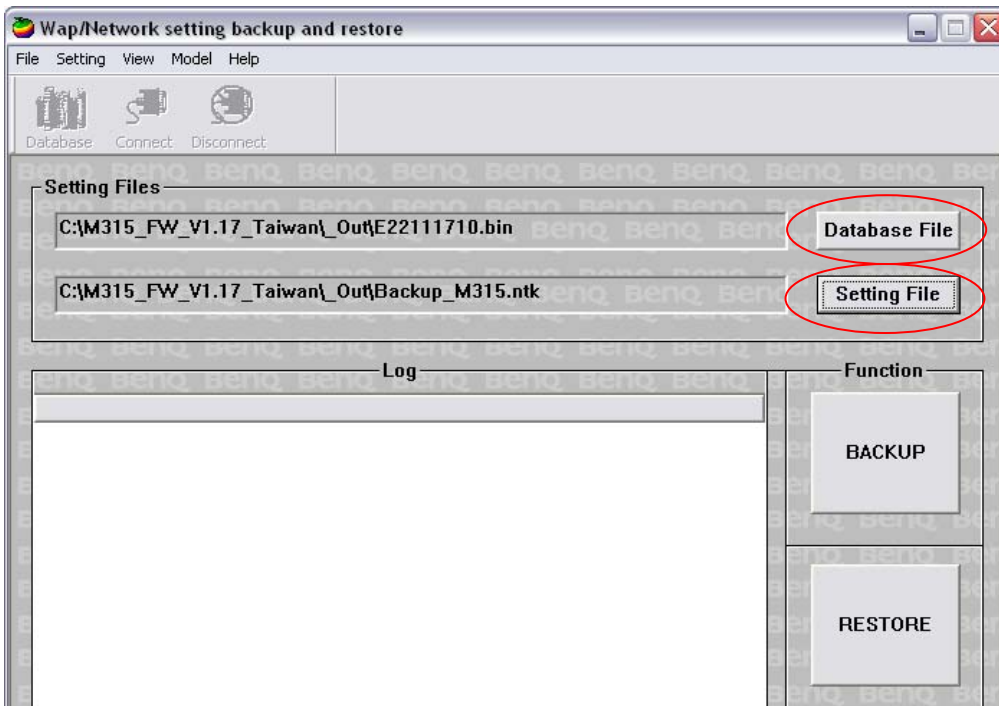


11 Backup and Restore of Wap and Network Setting

- Select Back and Restore of Wap and Network Settings option (View – Wap/Network Bkp/Restore):



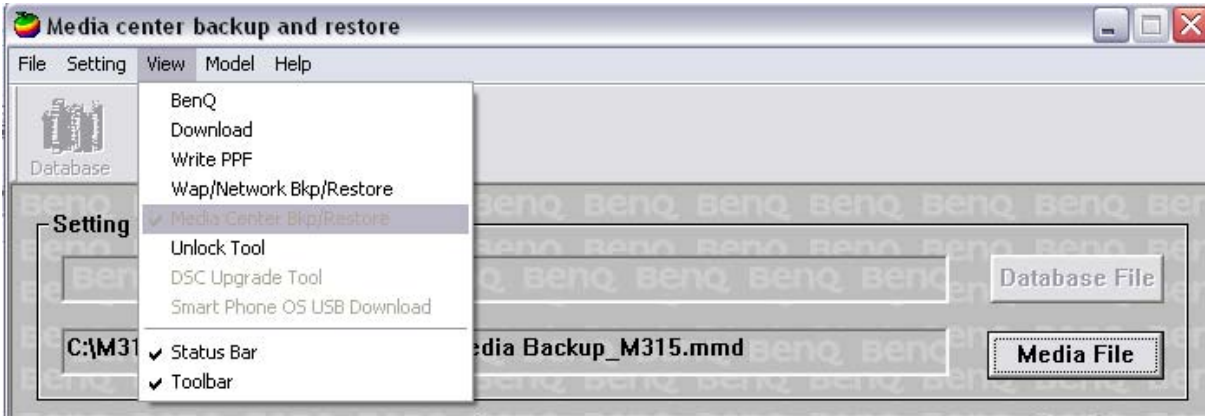
- Select Database File (example: E2211710.bin) and Setting File (create new txt file and rename it to ntk file for settings backup)



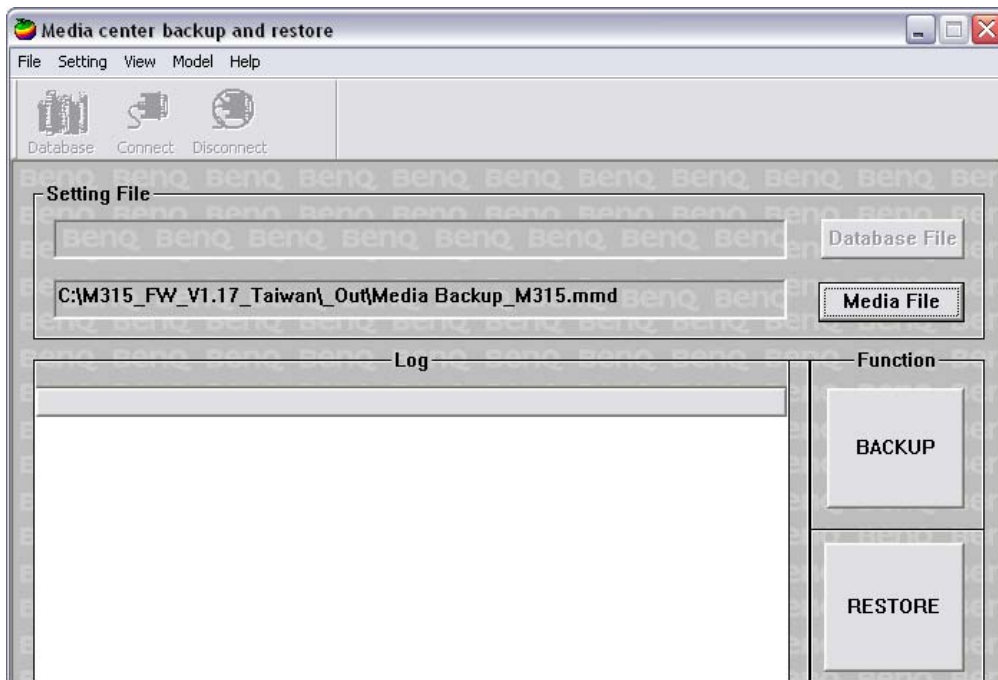
- Connect mobile phone with data cable. Phone must be switched off.
- Click to “Backup” button to start the transfer the settings into the selected file.
- Click to “Restore” button to start the transfer from selected file into handset.

12 Backup and Restore of Media Center content

- Select Back and Restore of Media center (View – Media center Bkp/Restore):



- Select **Media File** (create new txt file and rename it to mmd file)



- Connect mobile phone with data cable. Phone must be switched on.
- Click to “Backup” button to start the transfer the settings into the selected file.
- Click to “Restore” button to start the transfer from selected file into handset.

13 Unlock Tool

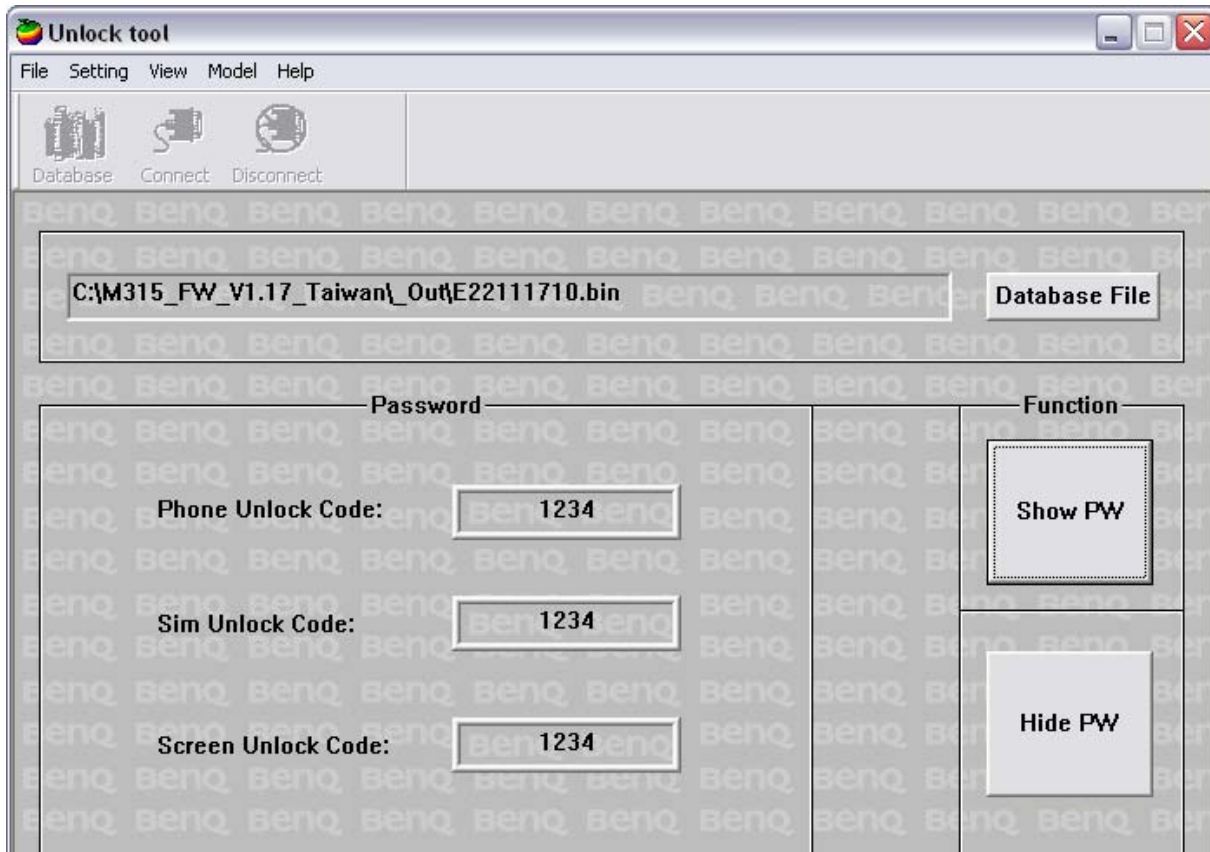
- Select Unlock tool function (View – Unlock Tool):



Select Database File (example: E22111710.bin)



- Click to “Show PW” button to get the codes.
- Unlock the codes in the mobile phone menu.
- Click to “Hide PW” button to hide the codes.



14 International Mobile Equipment Identity, IMEI

The mobile equipment is uniquely identified by the International Mobile Equipment Identity, IMEI, which consists of 15 digits. Type approval granted to a type of mobile is allocated 6 digits. The final assembly code is used to identify the final assembly plant and is assigned with 2 digits. 6 digits have been allocated for the equipment serial number for manufacturer and the last digit is spare.

S88 series IMEI label is accessible by removing the battery.

Re – use of IMEI label is possible by using a hair – dryer to remove the IMEI label.

Date code is shown on IMEI label: Detailed description on how to read date code is given in Annex 2.

To display the IMEI number, exit code and SW/HW version, key: * # 300 #
Code *#301# activates self diagnosis.

15 General Testing Information

General Information

The technical instruction for testing GSM mobile phones is to ensure the best repair quality.

Validity

This procedure is to apply for all from Siemens AG authorized level 2 up to 2.5e workshops.

Procedure

All following checks and measurements have to be carried out in an ESD protected environment and with ESD protected equipment/tools. For all activities the international ESD regulations have to be considered.

Get delivery:

- Ensure that every required information like fault description, customer data a.s.o. is available.
- Ensure that the packing of the defective items is according to packing requirements.
- Ensure that there is a description available, how to unpack the defective items and what to do with them.

Enter data into your database:

(Depends on your application system)

- Ensure that every data, which is required for the IRIS-Reporting is available in your database.
- Ensure that there is a description available for the employees how to enter the data.

Incoming check and check after assembling:**!! Verify the customers fault description!!**

- After a successful verification pass the defective item to the responsible troubleshooting group.
- If the fault description can not be verified, perform additional tests to save time and to improve repair quality.
 - Switch on the device and enter PIN code if necessary unblock phone.
 - Check the function of all **keys** including **side keys**.
 - Check the **display** for error in line and row, and for illumination.
 - Check the **ringer/loudspeaker** acoustics by individual validation.
 - Perform a **GSM Test** as described on page 36.

Check the storage capability:

- Check internal resistance and capacity of the battery.
- Check battery charging capability of the mobile phone.
- Check charging capability of the power supply.
- Check current consumption of the mobile phone in different mode.

Visual inspection:

- Check the entire board for liquid damages.
- Check the entire board for electrical damages.
- Check the housing of the mobile phone for damages.

SW update:

- Carry out a software update and data reset according to the master tables and operator/customer requirements.

Repairs:

The disassembling as well as the assembling of a mobile phone has to be carried out by considering the rules mentioned in the dedicated manuals. If special equipment is required the service partner has to use it and to ensure the correct function of the tools.

If components and especially soldered components have to be replaced all rules mentioned in dedicated manuals or additional information e.g. service information have to be considered

GSM Test:

With the availability of the GRT Test /Alignment software, this tool has to be used to perform the outgoing test!

>Connect the mobile/board via internal antenna (antenna coupler) and external antenna (car cradle/universal antenna clip) to a GSM tester

>Use a Test SIM

For Triple Band phones use a separate test case, if the test software allows only one handover.

Skip the GSM Band test cases if not performed by the mobile phone

Example: 1. Test file Band 1 = GSM900 / Band 2 = GSM1800
 2. Test file Band 1 = GSM1900

Internal Antenna				
Test case		Parameter	Measurements	Limits
1	Location Update	<ul style="list-style-type: none"> • GSM Band 1 • BS Power = -55 dBm • middle BCCH 	<ul style="list-style-type: none"> • Display check 	<ul style="list-style-type: none"> • individual check
2	Call from BS	<ul style="list-style-type: none"> • low TCH • highest PCL • BS Power = -75 dBm • middle BCCH 	<ul style="list-style-type: none"> • Ringer/Loudspeaker check 	<ul style="list-style-type: none"> • individual check
3	TX GSM Band 1	<ul style="list-style-type: none"> • low TCH • highest PCL • BS Power = -75 dBm • middle BCCH 	<ul style="list-style-type: none"> • Frequency Error • Phase Error RMS • Phase Error Peak • Average Power • Power Time Template 	<ul style="list-style-type: none"> • GSM Spec.
4	Handover to GSM Band 2 Including Handover Check			
5	TX GSM Band 2	<ul style="list-style-type: none"> • low TCH • highest PCL0 • BS Power = -75 dBm • middle BCCH 	<ul style="list-style-type: none"> • Frequency Error • Phase Error RMS • Phase Error Peak • Average Power • Power Time Template 	<ul style="list-style-type: none"> • GSM Spec.
6	Call release from BS			

External Antenna				
7	Call from MS	<ul style="list-style-type: none"> • GSM900 • high TCH • second highest PCL • BS Power = -75 dBm • middle BCCH 	<ul style="list-style-type: none"> • Keyboard check 	<ul style="list-style-type: none"> • individual check
8	TX GSM Band 1	<ul style="list-style-type: none"> • high TCH • second highest PCL • BS Power = -75 dBm • middle BCCH 	<ul style="list-style-type: none"> • Frequency Error • Phase Error RMS • Phase Error Peak • Average Power • Power Time Template 	<ul style="list-style-type: none"> • GSM Spec.
9	RX GSM Band 1	<ul style="list-style-type: none"> • high TCH • BS Power = -102 dBm • 50 Frames • middle BCCH 	<ul style="list-style-type: none"> • RX Level • RX Qual • BER Class Ib • BER Class II • BER Erased Frames 	<ul style="list-style-type: none"> • GSM Spec.
10	Handover to GSM Band 2 Including Handover Check			
11	TX GSM Band 2	<ul style="list-style-type: none"> • high TCH • second highest PCL • BS Power = -75 dBm • middle BCCH 	<ul style="list-style-type: none"> • Frequency Error • Phase Error RMS • Phase Error Peak • Average Power • Power Time Template 	<ul style="list-style-type: none"> • GSM Spec.
12	RX GSM Band2	<ul style="list-style-type: none"> • high TCH • BS Power = -102 dBm • 50 Frames • middle BCCH 	<ul style="list-style-type: none"> • RX Level • RX Qual • BER Class Ib • BER Class II • BER Erased Frames 	<ul style="list-style-type: none"> • GSM Spec.
13	Call release from MS			

Final Inspection:

The final inspection contains:

- 1) A 100% network test (location update, and set up call).
- 2) Refer to point 3.3.
- 3) A random sample checks of:
 - Data reset (if required)
 - Optical appearance
 - complete function
- 4) Check if PIN-Code is activated (delete the PIN-Code if necessary).

Basis is the international standard of **DIN ISO 2859**.

Use Normal Sample Plan Level II and the Quality Border 0,4 for LSO.

Remark: All sample checks must be documented.

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Annex 1

Test SIM Card

There are two different “Test SIM Cards” in use:

1) Test SIM Card from the company “**ORGA**”

Pin 1 number: 0000
PUK 1 : 12345678

Pin 2 number: 0000
PUK 2 : 23456789

2) Test SIM Card from the company “**T-D1**”

Pin 1 number: 1234
PUK : 76543210

Pin 2 number: 5678
PUK 2 : 98765432

Annex 2

Device Date Code overview

GSN rule:

(ex: GS11500001TG0)

GS 1 9 5 00001 TG0
 Big class Date Month Year S/N Factory

Code	Meaning	Content
D	Date	1~9, A=10, B=11, C=12, D=13, E=14, F=15, G=16, H=17, J=18, K=19, L=20, M=21, N=22, P=23, R=24, S=25, T=26, V=27, W=28, X=29, Y=30, Z=31 (Don't use: 0, I, O, Q, U)
M	Month	1=Jan, 2=Feb, 3=Mar, 4=Apr, 5=May, 6=Jun, 7=Jul, 8=Aug, 9=Sep, A=Oct., B=Nov, C=Dec
Y	Year	Last digit of Year (Christian era) ex. Year 2004 → "4"

Based on the definition above, GSC55... below means 2005/05/12.



16 Introduction of Service Repair Documentation Level 3 (basic) – S88

16.1 Purpose

This part of Service Repair Documentation is intended to carry out repairs on BenQ Mobile repair level 3basic (only for workshops without level 3 equipment (special agreement required)). The described failures shall be repaired in BenQ authorized local workshops only.

The level 3basic partners are obliged to send exchanged boards (SWAP) to the next higher Service Repair Partner.

All repairs have to be carried out in an ESD protected environment and with ESD protected equipment/tools. For all activities the international ESD regulations have to be considered.

Assembling/disassembling has to be done according to the latest S88 Level 1-3 repair documentation.

The Service Partner has to ensure that every repaired mobile Phone is checked according to the latest released General Test Instruction document (both documents are available in the Technical Support section of the C-market).

Check at least weekly C-market for updates and consider all S88 related Customer Care Information

The part number for the S88 is S88 where the last for letters specify the housing and software variant.

Scrap Handling: All Scrap information given in this manual are related to the SCRAP-Rules and instructions.

Attention: Consider the new "LEAD-FREE" soldering rules (available in the communication market), avoid excessive heat.

16.2 Scope

This document is the reference document for all BenQ mobile authorised Service Partners which are released to repair BenQ mobile phones up to level 2.5 light.

16.3 Terms and Abbreviations

17 List of available Level 3 (basic) parts

Product	Order Number	Description CM
S88	L50634-Z97-C553	CONN DC PWR PA05302-QNJ
S88	L50634-Z97-C633	CONN AXK7L20227
S88	L50634-Z97-C634	CONN AXK7L30227
S88	L50634-Z97-C635	CONN AXK734245
S88	L50634-Z97-C636	CONN BF1-0115
S88	L50634-Z97-C554	CONN ANT RF05301-PG
S88	L50634-Z97-C556	CONN BAT3PD2.5AB303Y-C0G1
S88	L50634-Z97-C558	CONN I/O 10P P0.5
S88	L50634-Z97-C637	CONN SIM BM05306-D18
S88	L50634-Z97-C638	CONN MEMORY 11TFC-001
S88	L50615-Z77-C287	SWI RF ANTENNA MS-147

18 Hardware requirements

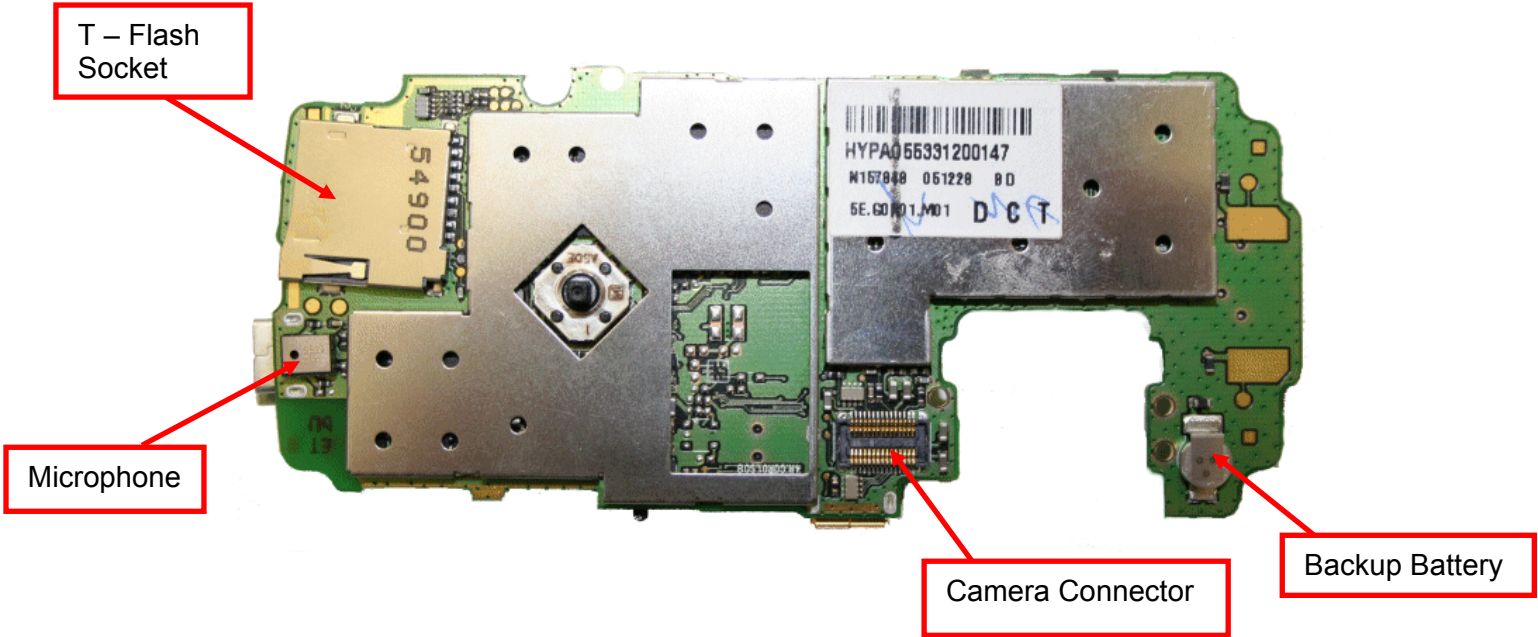
(According to General soldering information V1.3 - check C-market for updates)

Jigs, Tools and working materials for all described repairs:

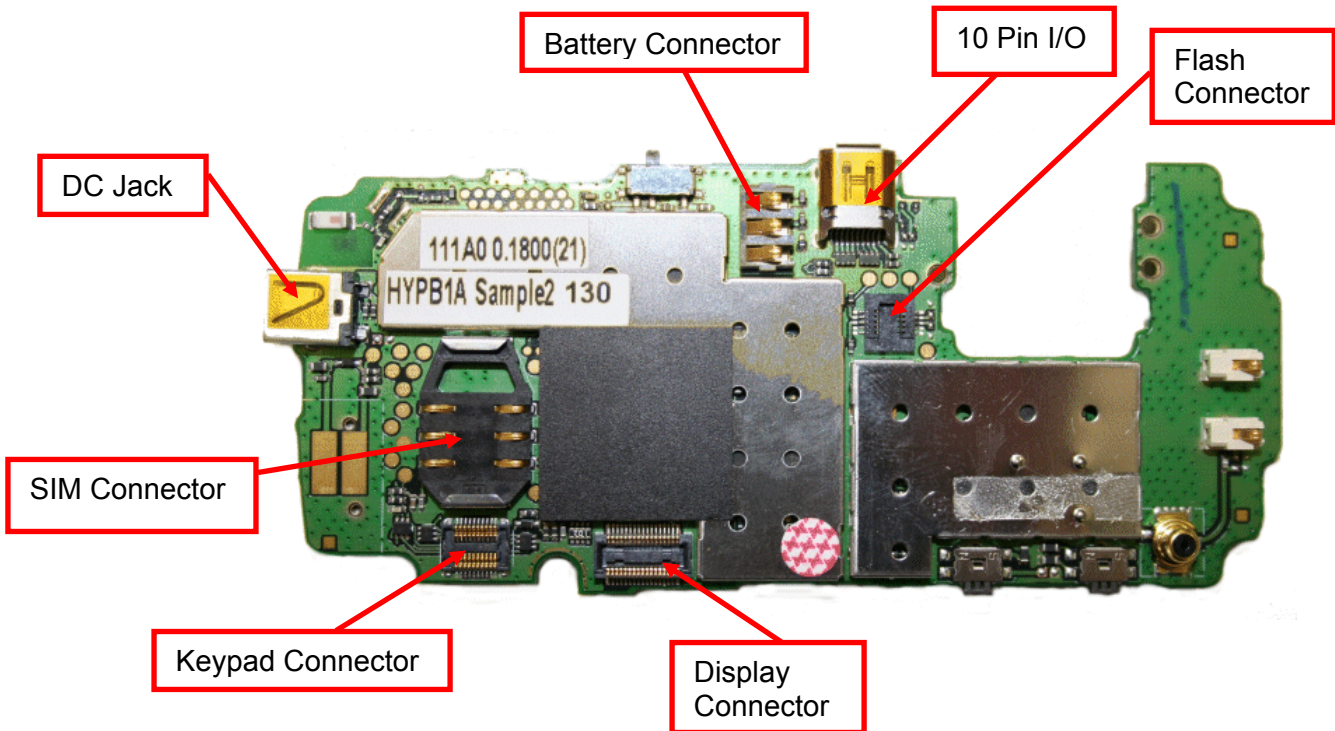
- hot air blower
- soldering gun
- tweezers
- flux
- solder

19 S88 Board Layout

Upper board side

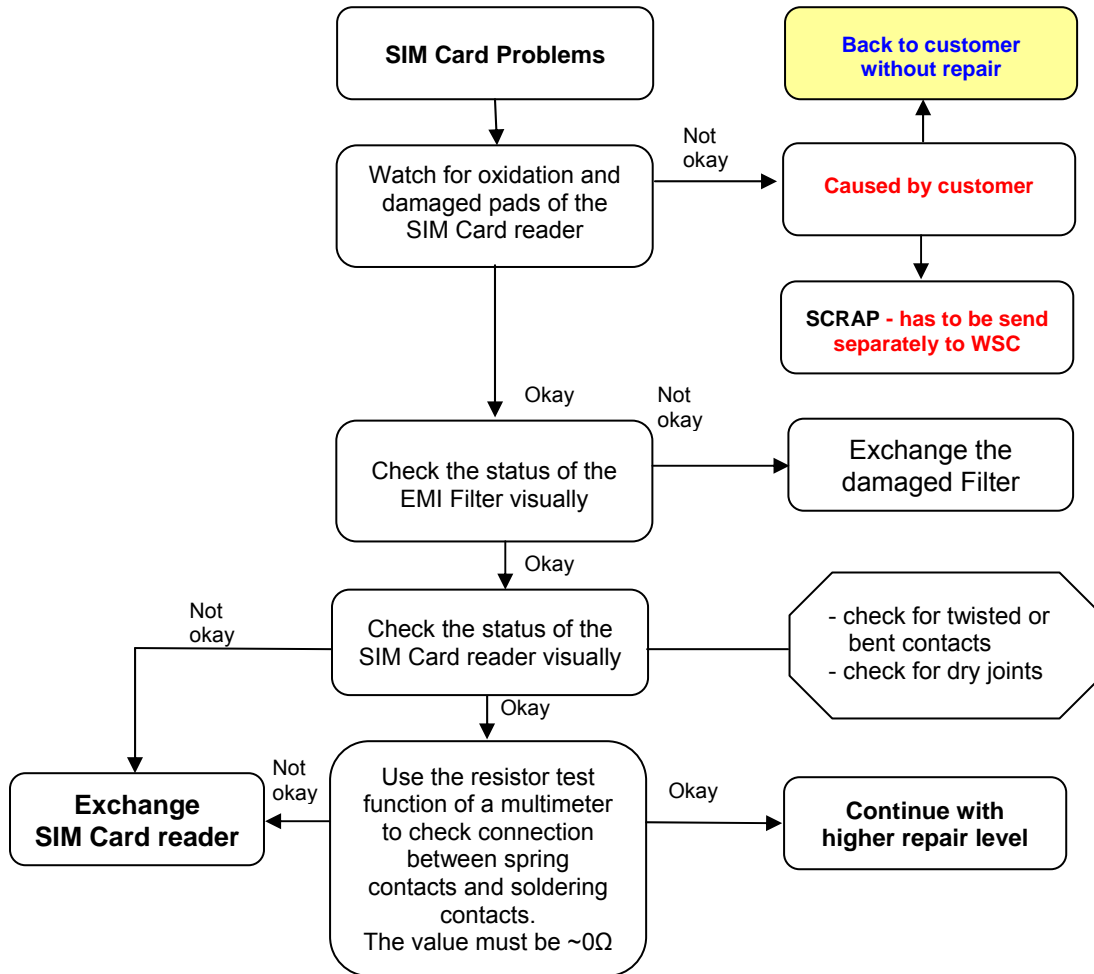


Lower board side



20 SIM Card Problems

Fault Symptoms	
Customer: Handset does not accept SIM card	GRT: Support in February 2006



Connector SIM Card Reader

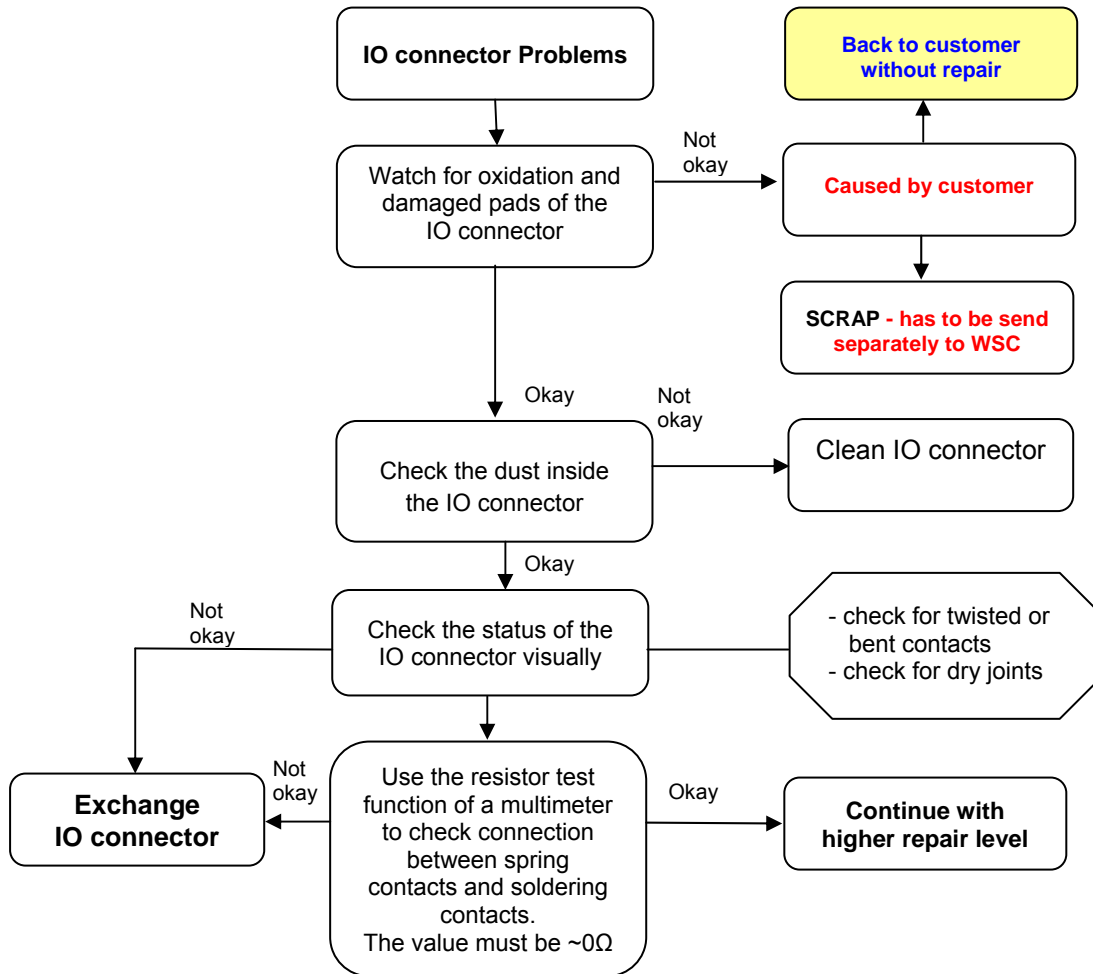
Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z97-C637
 E-commerce order name: CONN SIM BM05306-D18
 Soldering temperature: ~ 360°C TIP Temp.

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21 IO Connector Problems

Fault Symptoms	
Customer: Problems with external loudspeaker or microphone when using a car kit Problems with accessories connected at the IO connector	GRT: Support in February 2006



Connector IO Jack

Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z97-C558
 E-commerce order name: CONN I/O 10P P0.5

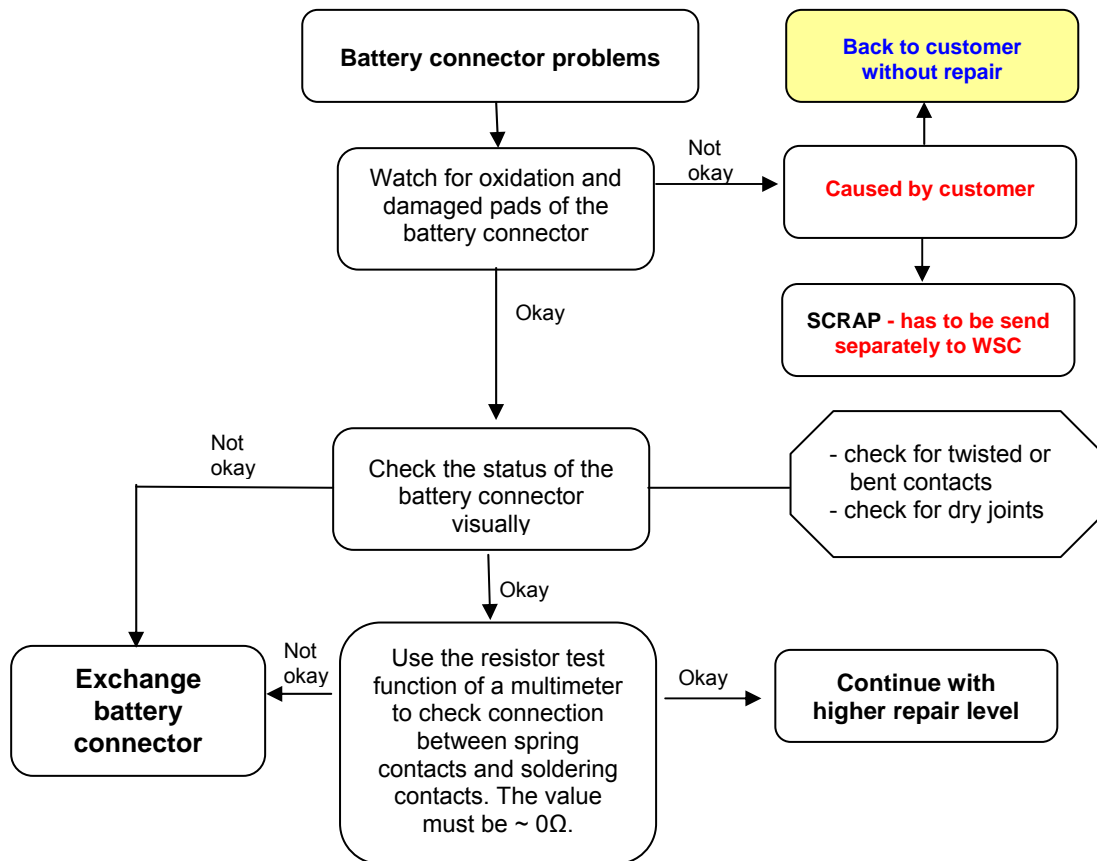
Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 47300 Interface/Data Interface/Mechanical Damage
 4B100 Interface/Headset Connector/Mechanical Damage

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22 Battery Connector Problems

Fault Symptoms	
Customer: Mobile does not switch on	GRT: No connection to GRT



Connector BATTERY

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z97-C556
 E-Commerce name: CONN BAT3PD2.5AB303Y-C0G1

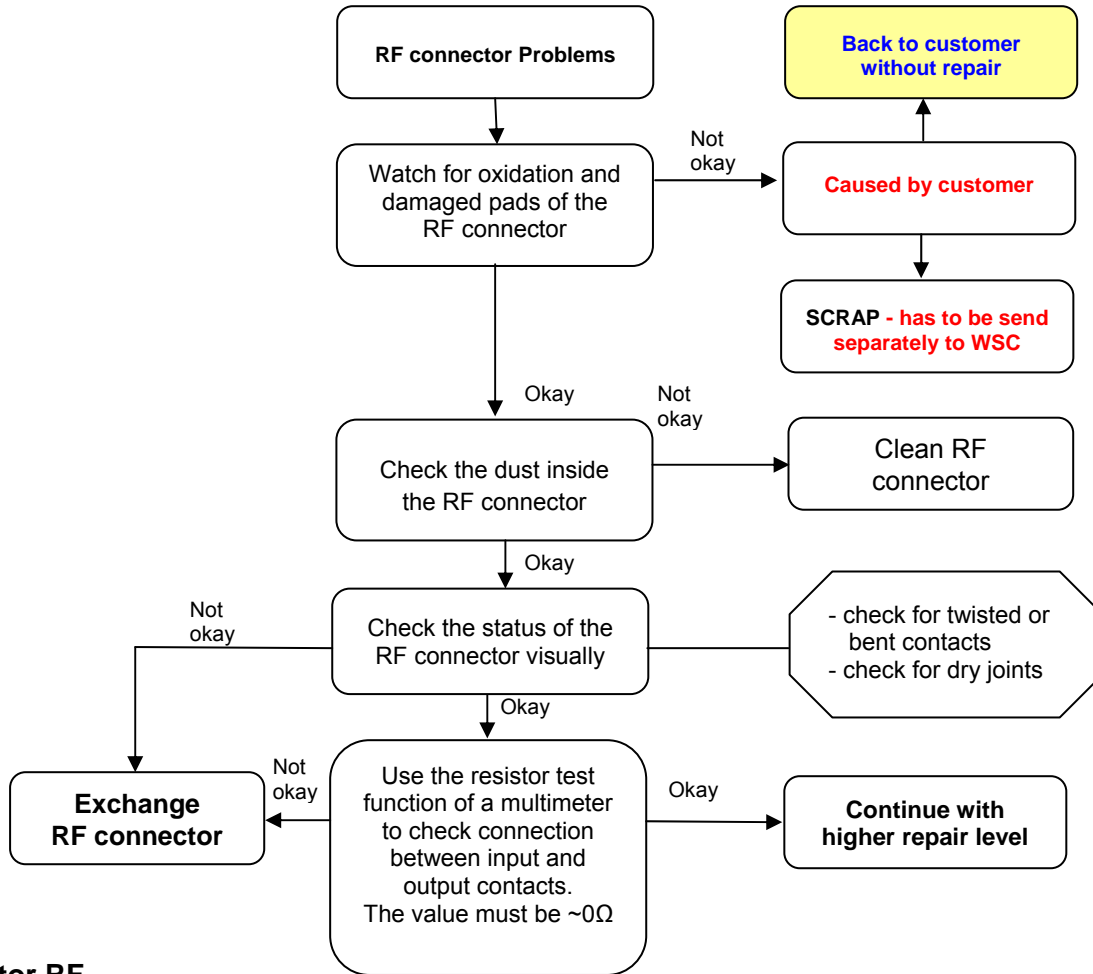
Soldering temperature: 240 - 255°C

IRIS Diagnose Code: 13000 Battery/Mechanical Damage

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23 RF Antenna Problems

Fault Symptoms	
Customer: Network search No location update possible	GRT: Failure by TX/RX measurements No location update possible



Connector RF

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

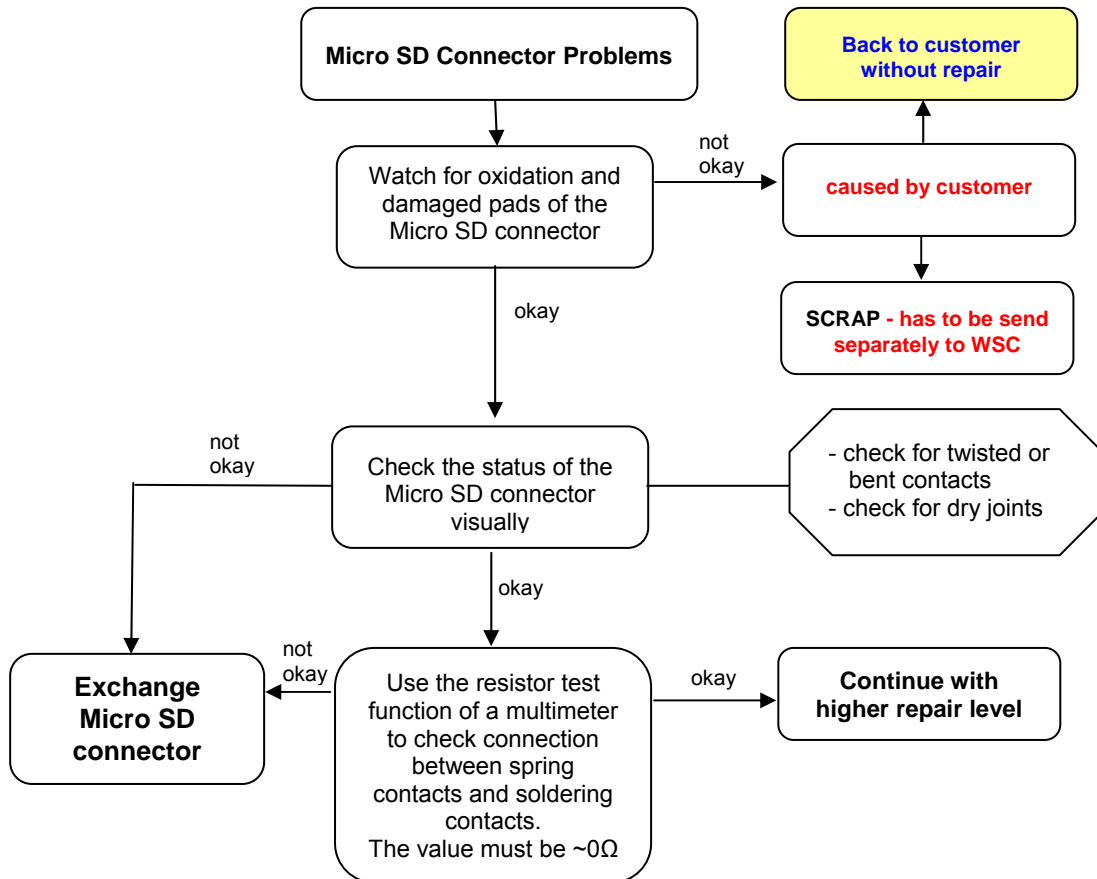
E-commerce order number: L50634-Z97-C554
 E-commerce name: CONN ANT RF05301-PG
 E-commerce order number: L50615-Z77-C287
 E-commerce name: SWI RF ANTENNA MS-147
 Soldering temperature: 240 - 255°C
 IRIS Diagnose Code:

81100 Radio / No Contact / Int. Antenna	81200 Radio / No Contact / Ext. Antenna
82100 Radio / Low Receiving Signal / Int. Antenna	82200 Radio / Low Receiving Signal / Ext. Antenna
83100 Radio / Dropped Calls / Int. Antenna	83200 Radio / Dropped Calls / Ext. Antenna
84100 Radios / Call Setup / Int. Antenna	84200 Radio / Call Setup / Ext. Antenna

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24 Micro SD Connector Problems

Fault Symptoms	
Customer: MMC malfunction	GRT: Tbd.



Connector MMC

Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z97-C638
 E-commerce order name: CONN MEMORY 11TFC-001

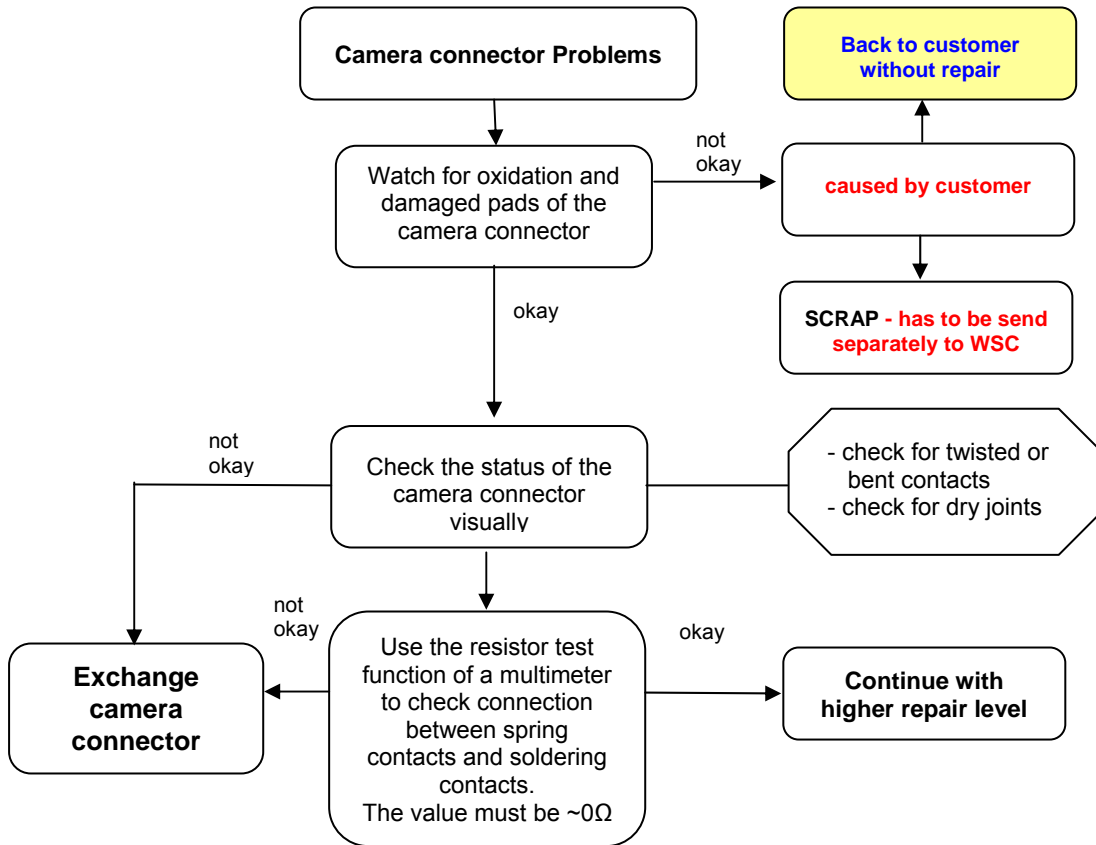
Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 4E000 Interfaces/ Memory Card Rerader

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25 Camera Connector Problems

Fault Symptoms	
Customer: Camera malfunction	GRT: Tbd.



Connector CAMERA

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z97-C634
 E-commerce order name: CONN AXK7L30227

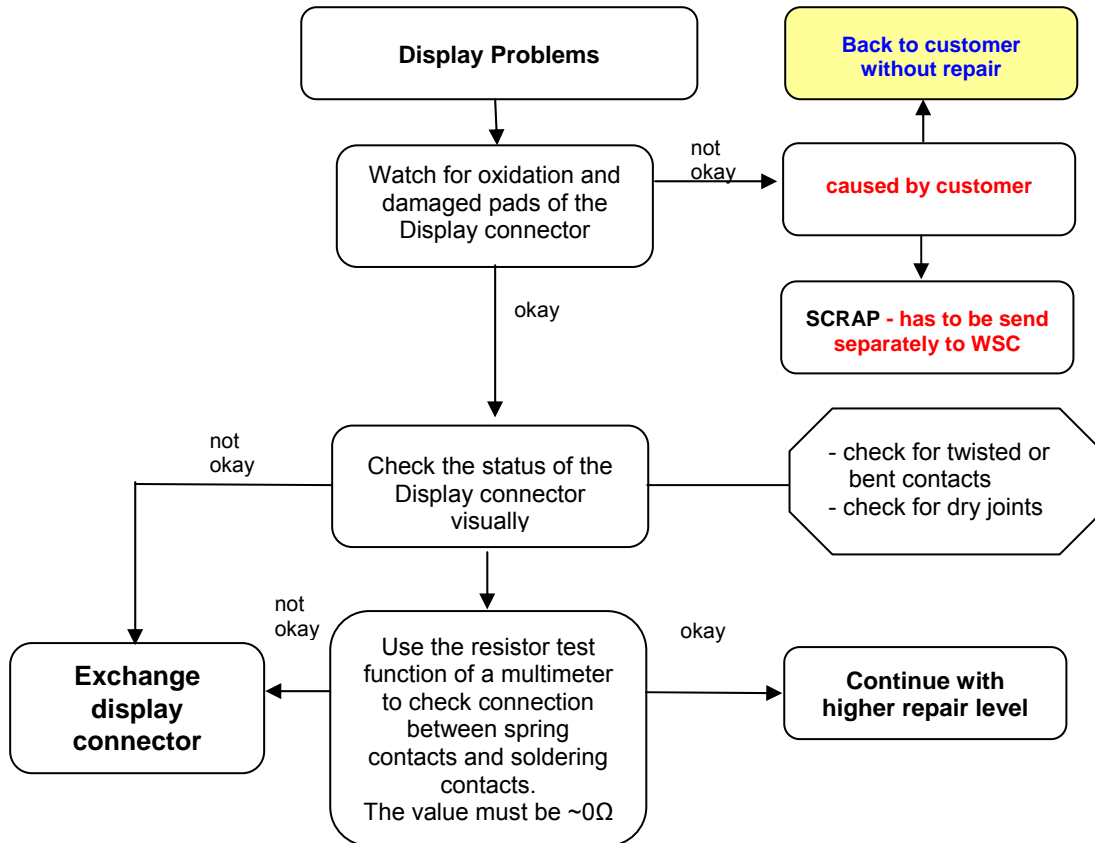
Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: BA000 Accessories / Camera

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26 Display Problems

Fault Symptoms	
Customer: Display problems	GRT: Current measured failed



Connector DISPLAY

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z97-C635

E-commerce order name: CONN AXK734245

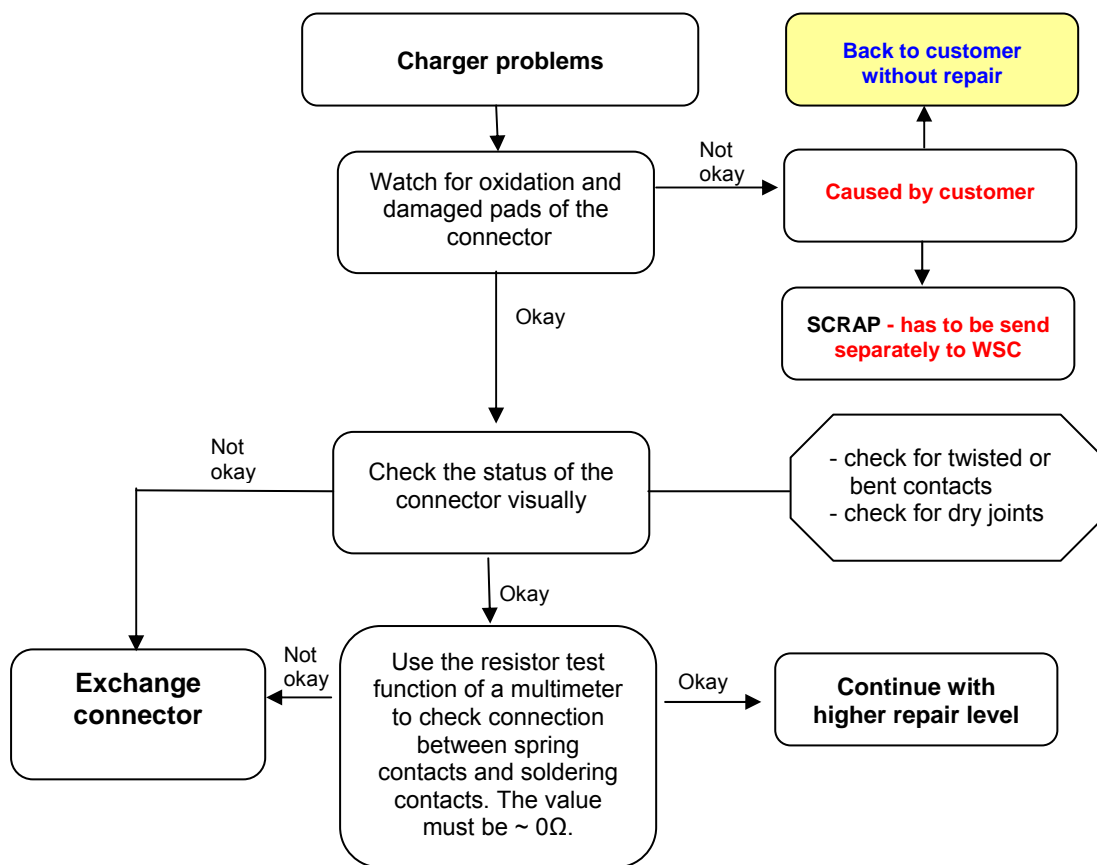
Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 21000 Display / Performance
22000 Display / Background Illumination

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27 Charger Problems

Fault Symptoms	
Customer: Charger Problems	GRT: Tbd.



E-commerce order number: L50634-Z97-C553

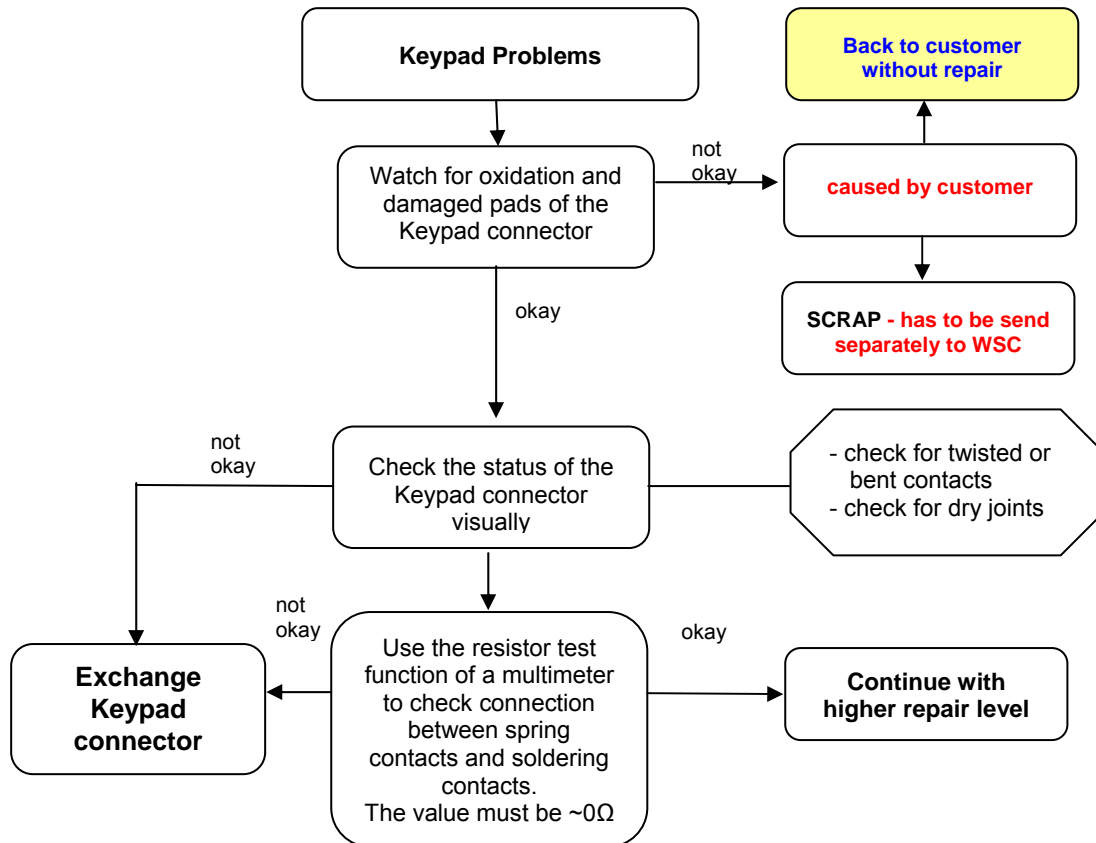
E-commerce order name: CONN DC PWR PA05302-QNJ

IRIS Diagnose Code: 46100 Interface/Charging Connector/Mechanical Damage

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28 Keypad Problems

Fault Symptoms	
Customer: Keypad problems	GRT: Current measured failed



E-commerce order number: L50634-Z97-C633
 E-commerce order name: CONN AXK7L20227

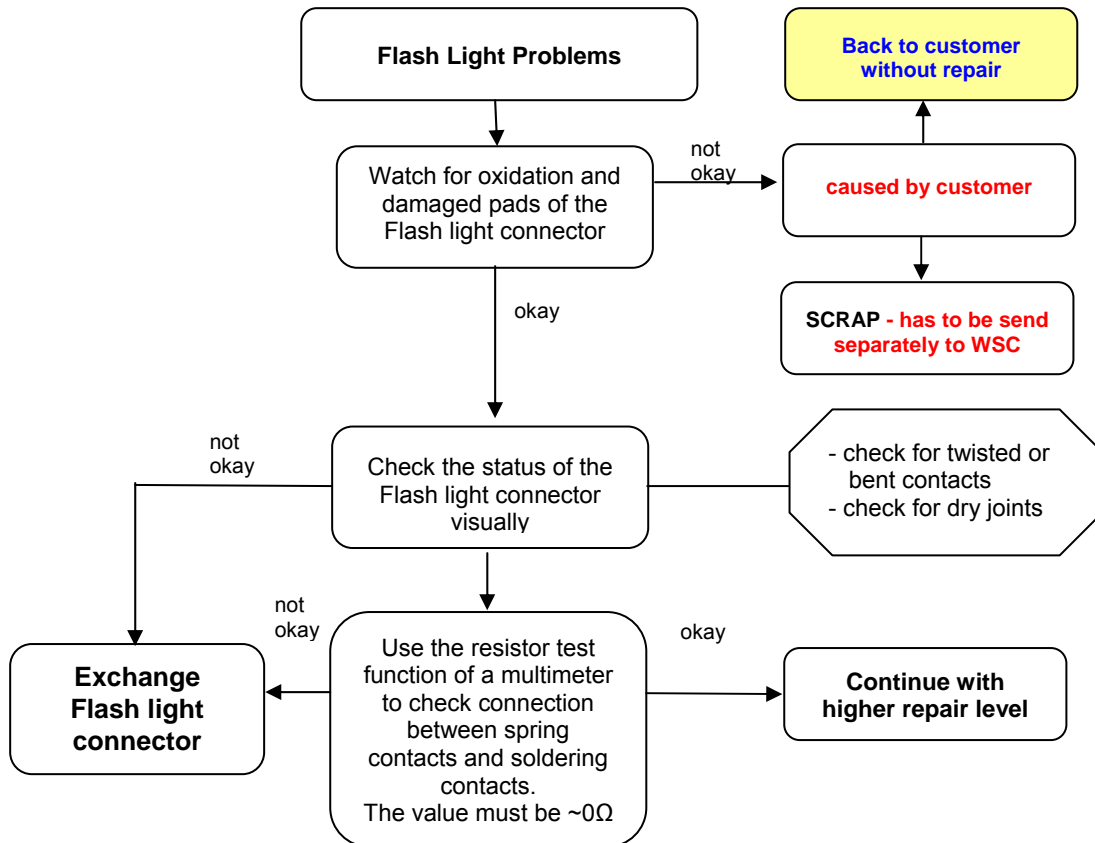
Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 21000 Display / Performance
 22000 Display / Background Illumination

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29 Flash light Problems

Fault Symptoms	
Customer: Flash light problems	GRT: Current measured failed



E-commerce order number: L50634-Z97-C636
 E-commerce order name: CONN BF1-0115

Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 21000 Display / Performance
 22000 Display / Background Illumination